

JADE

Computer Products

THE BIG Z

REVISION C

2 MHz OR 4 MHz SWITCHABLE Z-80 CPU WITH ON-BOARD SERIAL I/O PORT

INTRODUCTION

The **JADE BIG Z Z80** Microprocessor CPU board is a very stable and powerful CPU, designed for the S-100 bus and in reasonable conformity with the proposed IEEE S-100 Bus Standard.

The **Big Z** CPU provides on-board EPROM and on-board serial communications via an RS232C standard interface which supports transmit and receive data and one standard handshake line.

The **Big Z** CPU board has been manufactured to the most exacting specifications, using the highest quality material and components conservatively rated for long life. As such, it may be expected to give you many thousands of hours of useful active service.

If you have purchased the **Big Z** as an assembled and tested unit, you should know that it has passed rigorous tests, running in a real-time disk-based

environment and executing the most complicated programs we can devise. Before it goes out the door, every assembled and tested **Big Z** must prove itself to our picky engineering personnel.

Although any component can fail, most ICs die in their infancy, and the burn-in time each **Big Z** receives insures that we catch practically all of these infant mortalities.

If you have purchased the **Big Z** as a kit, we strongly urge you to read this manual in its entirety before attempting to construct the board. Although there are about as many ways of assembling a board as the tenth power of the components on it, if you will follow the assembly instructions step-by-step, construction will be easier for you and much more pleasurable for both of us.

FEATURES

On-board 2708/2716/2732 EPROM can be addressed to any 1K, 2K, or 4K boundary. * Power-on jump directly to the on-board EPROM. * Optional wait state for on-board EPROM. * On-board EPROM may be used in shadow mode (accessed only after power-on or reset). * Allows full 64K RAM memory to be used. * On-board 8251 USART for synchronous or asynchronous RS232 operation. * Independent crystal-controlled baud rate generator provides all standard baud rates from 110 to 9600. * Switch-selectable 2 or 4 MHz operation. * Optional M1 wait states can be generated. * Automatic MWRT generation if a front panel is not used, automatically disabled if a front panel is connected. * DMA capability. * Latched data output bus provides additional data hold time for reliable operation with all

device types. * Straight-through address and data paths provide improved read access times for I/O and memory devices. * On-board serial port switch-selectable to any pair of I/O port locations from 00 through FE hex. * Reverse channel capability on USART allows use with buffered peripherals or devices with "not ready" indication. * Front panel data cable interface. * Fully buffered S-100 interface. * Separate voltage regulators (no diodes) assure a clean, stable power supply. * Intelligent, clean layout of PC board. * Reflow soldered, plated, and fully masked PC board. * Gold-plated S-100 bus connector is Imsai standard. * Complete 1K monitor software listing included in manual. * Fully warranted by **JADE**, one of the largest microcomputer product suppliers in the world.

FUNCTIONAL DESCRIPTION

Figure 1-1 is a block diagram describing the functional blocks contained on the **JADE Big Z** CPU. The following sections describe each of the blocks in Figure 1-1.

Z80 CPU

At the heart of the Big Z is the powerful Z80 microprocessor which provides the major control signals required to read and write to memory and I/O ports. Also generated by the Z80 are a 16-bit address bus and an 8-bit bidirectional data bus.

OSCILLATOR

The oscillator is a crystal-controlled circuit which generates Phi1 and Phi2 clock signals for the S-100 bus, the Clock* S-100 signal, and the internal system clock. Also involved with this circuitry are the Reset and Power-on Clear signals.

STATUS AND CONTROL BUFFERS

The status and control buffers provide the drive for the various S-100 bus status and control signals. During a DMA operation (when BUSAK is high on the Z80 chip), or during maintenance functions, the status and control buffers are tri-stated, allowing a DMA device to control the bus as a temporary bus master.

ADDRESS BUFFER

The address buffer is a 16-bit tri-state buffer which drives the 16-bit address to the S-100 bus. It also is tri-stated during DMA operations or maintenance functions.

DATA OUT BUFFER

The data out buffer is an 8-bit tri-state buffer which drives the 8 data out signals to the S-100 bus. Data is gated out to the S-100 bus only during memory write or I/O output cycles. The data out buffer is tri-stated during DMA operations or maintenance functions.

DATA IN BUFFER

The S-100 data in bus is provided to the Z80 during read memory or I/O input bus cycles by the data in

buffers. These buffers are disabled during write memory or I/O output cycles, and for DMA operations. They may also be disabled by the following conditions;

- RUN and SS (Single Step) low (false) at pins 71 and 21 of the S-100 bus.

- On-board EPROM selected during a memory read operation.

- USART selected during an I/O operation.

- Power-on jump enabled and Power-On Latch (2 sections of U10) is set.

MEMORY DECODE AND CONTROL

The memory decode and control circuitry decodes the high-order address bits from the internal address bus and selects the EPROM. This block also generates the signals required to disable the data in buffers and interacts with the Shadow option circuitry to phantom out the EPROM.

EPROM

The on-board EPROM can be either a 1K (2708-type), 2K (2716 or TMS2716 type), or 4K (2732-type) EPROM. The EPROM may be switch selected for any 1K, 2K, or 4K boundary, depending on the type of EPROM installed.

I/O ADDRESS DECODE AND CONTROL

The I/O address decode and control circuitry decodes the lower 8 bits of the internal address bus to determine which ports are being accessed during I/O instructions. This block also interacts with the EPROM select circuitry and the circuitry which disables the data in buffers.

SERIAL I/O

The serial I/O provides synchronous and asynchronous communications via RS232C level interfaces. Included in this block is the crystal-controlled oscillator and baud rate generator for the 8251 USART.

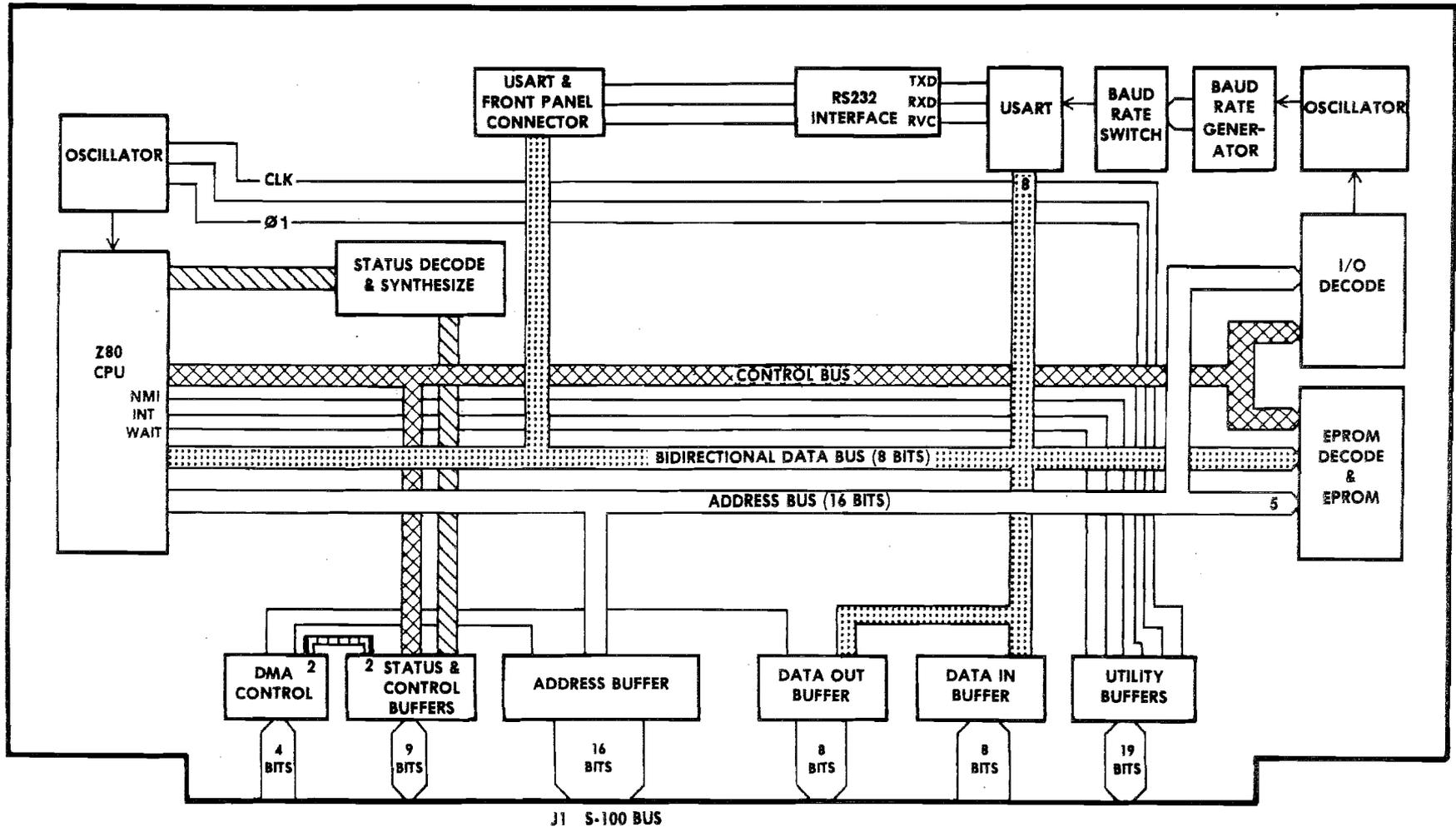


Figure 1.1

J1 S-100 BUS

TECHNICAL DESCRIPTION

S-100 INTERFACE

Address Bus

The internal address bus is driven to the S-100 bus by tri-state buffers U25, U36, and a portion of U35. These buffers (8T97, 8097, or 74367 ICs) are tri-stated during DMA operations or maintenance functions. This is accomplished via one of the inverter sections of U18, which is driven by the ADDSB* signal on pin 22 of the S-100 bus. Normally, the input to the inverter is held high by a pullup resistor on pin 1 of U18, which forces a low output from the inverter on pin 2. This low level signal is routed to the enable pins on the address buffers.

When ADDSB* goes true (low), the output on pin 23 of the inverter U18 goes high, disabling the address buffers.

Data In Bus

The internal bidirectional data bus is driven from the S-100 bus by tri-state buffers U38 and a portion of U29. These buffers are enabled only during read memory or I/O input cycles. They are also disabled by the following conditions:

1. SSWDSB* is low (true) at pin 53 of the S-100 bus. This signal is one of the inputs to NAND gate U22, along with sWO*. It is normally held high (false) by pullup resistor pack U31.
2. RUN or SS on pins 71 and 21 respectively of the S-100 bus is low (false). These signals are held normally high by pullup resistors in resistor pack U31. They are inputs to NOR gate U8. This NOR output is NORed with the NAND of SSWDSB* and sWO* by another section of U8, and this signal is applied to pin 3 of the 3-input NAND gate U4, where it is Nanded with the signals discussed below.
3. On-board EPROM is selected during a memory read operation. The signal EPS*, which is the output from pin 6 of AND gate U7 is applied to pin 4 of NAND gate U4.
4. On-board USART selected during an I/O operation (either input or output cycle). The DCS* signal, generated as the output of OR gate U14 at pin 8, is applied to pin 5 of NAND gate U4, whose output drives the tri-state input of data in buffers U38 and U29.
5. Power-on Jump is enabled and the Power-On Latch (2 sections of U10) is set.

Data Out Bus

The internal data bus is provided to the S-100 DO (data out) bus for memory write or I/O output cycles by tri-state buffers U37 and a portion of U25. The DODSB* signal on pin 23 of the S-100 bus will disable these buffers when it goes low (true). It is provided to the tri-state control inputs of the buffers via inverter U18. The input to inverter U18 on pin 13 is held normally high by pullup resistor R1, forcing the output of the inverter to be low, thereby enabling the buffers. When DODSB* goes true (low), the pullup resistor is overcome and the tri-state inputs of the buffers go high, disabling (tri-stating) these buffers.

The input to the data out buffers are provided by latches U27 and U26. Data is passed through the latches by the high level of Phi2 clock. The falling edge of Phi2 clock disables the latches.

A true (low) signal at DODSB* will tri-state the data out bus for DMA or maintenance functions.

Status Signals

The primary status signals sM1, sOUT, sINP, sMEMR, and sWO* are provided to the S-100 bus via tri-state buffer U39. U39 is tri-stated by STADSB*, on pin 18 of the S-100 bus, going low (true). Normally, a pullup resistor holds the input to inverter U30 on pin 1 high, forcing the output of inverter U30 on pin 2 low, enabling the buffer at U39. When STADSB* goes true (low), the output of the inverter goes high, tri-stating the U39 buffer.

sM1 on pin 44 of the S-100 bus is provided by the CPU through buffer U39 and inverter U30. It is derived from the Z80's M1* signal, on pin 27 of the CPU. This signal is applied to pin 9 of inverter U30. The output of U30, pin 8, will be high when the Z80 M1* signal is true (low). The output of U30 is applied to input pin 14 of buffer U39 and is transferred to the S-100 bus from output pin 13 of buffer U39, provided that U39 is not tri-stated by a true (low) signal on STADSB*.

sM1 signals that the processor is fetching an instruction op code; therefore, it signals an opcode fetch cycle.

sOUT on pin 45 of the S-100 bus is provided by the CPU through buffer U39, AND gate U41, and inverters U18 and U30. It is derived from the Z80 WR* and IORQ* signals. These outputs from the Z80, on pins 22 and 20 respectively, are inverted by U18 and U30. The outputs

of these inverters, on pins 8 and 10 respectively of U18 and U30, will be high when WR^* and $IORQ^*$ are true (low). If both of these outputs are high—meaning that WR^* and $IORQ^*$ are true—the output of AND gate U41, on pin 11, will also be high. This signal is output to pin 12 of U39 and is transferred to the S-100 bus from U39 output pin 11, provided U39 is not tri-stated by $STADSB^*$ being true (low).

$sOUT$ signals an output to an I/O port; therefore, it may be referred to as an I/O output cycle signal.

$sINP$ on pin 46 of the S-100 bus is provided by the CPU through buffer U39, latch U40, AND gate U41, and inverter U30. It is derived from the Z80's RD^* and $IORQ^*$ signals. These outputs from the Z80, on pins 21 and 20 respectively, are applied to U30 inverter pins 3 and 11. The outputs of the inverter, on pins 4 and 10 respectively, are applied to AND gate U41 on input pins 10 and 9. When the outputs of inverter U30 are high (Z80 RD^* and $IORQ^*$ signals are low (true)), the output of AND gate U41, on pin 8, will be high. This signal is applied to the input of U40 latch on pin 7. Now, when $PSYNC$ is high, the signal is clocked through U40, being output on pin 9, and is applied to buffer U39 input pin 10. The signal is transferred through the buffer, output on pin 9, to S-100 bus pin 46, provided U39 is not tri-stated by $STADSB^*$ being true (low):

$sINP$ signals an input from an I/O port; therefore, it may be referred to as an I/O input cycle signal.

$sMEMR$ on pin 47 of the S-100 bus is provided by the CPU through buffer U39, latch U40, AND gate U41, and inverters U18 and U30. It is derived from the Z80's RD^* and MRQ^* signals. These outputs from the Z80, on pins 21 and 19 respectively, are applied to inverters U30 and U18, on input pins 3 and 3 respectively. The output of these inverters, on pins 4 and 4 respectively, will be high when the Z80 signals RD^* and MRQ^* are true (low). The outputs of the inverters are applied to input pins 5 and 4 of AND gate U41. When both of these inputs are high, the output of U41, on pin 6, will be high. This output is applied to input pin 6 of U40. Now, when $PSYNC$ is high, the signal is clocked through the latch and is output on pin 10 of U40. This output is applied to input pin 6 of buffer U39. It passes through the buffer, is output on pin 7, and is applied to S-100 pin 47, provided that $STADSB^*$ is not active (low).

$sMEMR$ signals a read from memory; therefore, it may be referred to as a memory read cycle signal.

sWO^* on pin 97 of the S-100 bus is provided by the CPU through buffer U39, latch U40, NAND gate U22, and inverter U18, together with inverter U30 and AND gate U41. It is derived from the Z80's RD^* and $INTA^*$ signals, where $INTA^*$ is derived—itsself—from the Z80 signals $M1^*$ and $IORQ^*$.

Z80 signal RD^* , on pin 21 of the CPU, is applied to input pin 2 of NAND gate U22. The other input pin is

driven by the output of inverter U30, pin 6. The input to this inverter is the output of AND gate U41. U41 ANDs $IORQ^*$ with $M1^*$. These signals are provided from the Z80's $IORQ^*$ and $M1^*$ signals on pins 20 and 27 respectively of the CPU.

When RD^* is false (high) and $IORQ^*$ and $M1^*$ are both false (also high), the output of NAND gate U22, pin 3, will go low. This low is applied to latch U40 on pin 3 and is clocked through the latch by $PSYNC$, being output on U40 pin 15. This output is applied to U39 buffer input pin 4, is transferred through the buffer to pin 5, and output to S-100 bus pin 97 as sWO^* . Note that the following conditions must be met for sWO^* to be true: the processor is not in a read cycle (RD^* is false—high), and neither is it in an Interrupt Acknowledge cycle ($IORQ^*$ ANDed with $M1^*$ is false).

sWO^* signals that the processor is not in a data input cycle. It is used as an early indication that a write operation will take place.

Other Status Signals

The IEEE-defined status signal $sXTRQ^*$ is not supported by the Big Z CPU. This signal is used to request a 16-bit wide input or output, and gangs the DO and DI buses together to form a single 16-bit bidirectional data bus. Since the Big Z is not a 16-bit processor, this signal protocol is not implemented.

$sINTA$ on pin 96 of the S-100 bus is provided by the CPU through buffer U6, AND gate U41, and inverter U30. It is derived from the Z80's $IORQ^*$ and $M1^*$ signals. These outputs from the Z80, on pins 20 and 21 respectively, are inverted by inverter U30. The signals are applied to input pins 11 and 9 of U30, and output on pins 10 and 8, respectively, as inverted signals. They are then applied to input pins 1 and 2 of AND gate U41. When the Z80 $IORQ^*$ and $M1^*$ are both true (low), the outputs of both inverters will be high. These high signals, applied to AND gate U41, result in a high being output on pin 3 of U41. This is applied to buffer U6 input pin 4, transferred through the buffer, output on pin 4, and applied to S-100 bus pin 96 as $sINTA$, provided that $CCDSB^*$ is false (high).

$sINTA$ signals that the processor is acknowledging an interrupt request from a peripheral device; therefore, it may be referred to as an interrupt acknowledge signal.

$sHLTA$ on pin 48 of the S-100 bus is provided by the CPU through buffer U17 and inverter U18. It is derived from the Z80's $HLTA^*$ signal on pin 18 of the CPU. $HLTA^*$ is applied to pin 5 of inverter U18, where it is inverted and output on pin 6 as $HLTA$. $HLTA$ is applied to buffer U17, input pin 6, is transferred through the buffer, and output on pin 7, where it is applied to S-100 bus pin 48. Buffer U17 is always enabled, since the tri-state inputs are grounded.

Control Signals—Output

There are five control signals defined by IEEE as control outputs. These are: *pSYNC*, *pSTVAL**, *pDBIN*, *pWR** and *pHLDA*.

*pSTVAL** is not implemented on the Big Z CPU. This is defined as a signal which, in conjunction with *pSYNC*, indicates that stable address and status information may be sampled from the bus in the current cycle. For Big Z applications, it is redundant and is therefore not implemented.

pSYNC is generated by one-shot U5, which is clocked by the Z80 signals *IORQ**, *RFS** and *MRQ**. *pSYNC* is transferred to pin 76 of the S-100 bus through buffer U6, which may be tri-stated by the signal *CCDSB**.

Z80 *RFSH** is applied directly to pin 4 of NAND gate U10, where it is NANDed with *MRQ*. *MRQ* is derived from the Z80 *MRQ** through inverter U18. *MRQ**, on pin 19 of the CPU, is applied to U18 pin 3, inverted, and output on pin 4 as *MRQ*. *MRQ* is applied to input pin 5 of NAND gate U10. When the Z80 signal *MRQ** is true (low), and *RFSH** is false (high), both inputs of the NAND gate U10 will be high, resulting in a low output from pin 6. This output is NANDed by gate U4 with *IORQ** from the Z80 pin 20. The output of U4 at pin 12 is applied to one-shot U5. The multivibrator clocks out, with its timeout period being determined by C24, a 100 picofarad capacitor, and R2, a 2.7K ohm resistor. The timeout, with these values, is approximately 270 nanoseconds. The output of the U5 multivibrator, on pin 6, is applied to U6 buffer input pin 10. It is transferred through U6 to output pin 9, and from there to the S-100 bus pin 76 as *pSYNC*.

pSYNC is only high during the first part of a memory or I/O cycle due to the effect of multivibrator U5. It is used to indicate the start of a new bus cycle, and is provided for those S-100 devices that look at status information during this time as per 8080 device conventions.

pDBIN on pin 78 of the S-100 bus is provided by the CPU through buffer U6 as an OR of Z80 signals *RD** and *IORQ** being—either of them—true. Z80 signal *RD**, on pin 21 of the CPU, is inverted by inverter U30. The output of U30 on pin 4 is applied to input pin 1 of OR gate U14. The other input to this OR gate, pin 2, is derived from the output of AND gate U41, which ANDs together *IORQ** and *M1** both true to generate *INTA* (Interrupt Acknowledge). Either *INTA* or *RD** true will generate a high output from OR gate U14, pin 3. This is applied to U6 buffer input pin 6, transferred through the buffer to output pin 7, and drives S-100 bus pin 78 (*pDBIN*), provided that the buffer is not tri-stated by a true condition of *CCDSB**.

pDBIN signals that the processor is in a data input

cycle, either I/O or memory read; therefore, it is a generalized read strobe gating data from an addressed bus slave onto the data in bus.

*pWR** on pin 77 of the S-100 bus is provided by the CPU through buffer U6 as a slightly delayed *WR** signal from the Z80 CPU. Z80 signal *WR**, on pin 22 of the CPU, is applied to inverter U18. The output of U18 on pin 8 is applied to both inputs of OR gate U8 on pins 5 and 6. The output of this OR gate on pin 4 is applied to buffer U6 input pin 2, is transferred through the buffer to output pin 3, where it is driven to S-100 bus pin 77, provided that buffer U6 is not tri-stated by *CCDSB** being true.

*pWR** signals that the processor is in a data output cycle, either I/O or memory; therefore, it is a generalized write strobe that writes data from the bus into an addressed bus slave.

pHLDA on pin 26 of the S-100 bus is provided by the CPU through buffer U17. It is simply an inverted Z80 *BUSAK**. *BUSAK** from the Z80, on pin 23, is applied to inverter U15 pin 5. The output of this inverter is applied to buffer U17 input pin 10, is transferred through the buffer, exits on pin 9, and is then applied to S-100 bus pin 26. When *BUSAK** is true (low) on the Z80, *pHLDA* will be high on the S-100 bus.

pHLDA is the hold acknowledge signal that indicates to the highest priority device that is requesting a hold that the CPU is relinquishing control of the bus. When a device requests a hold and is acknowledged by the CPU, the Z80 tri-states its own data and address busses and generates *BUSAK** true, which is passed to the S-100 bus as *pHLDA*. This signal is always passed onto the bus, since the tri-state inputs of buffer U17 are grounded and the buffer is always enabled.

Control Signals—Input

There are six control input lines defined by IEEE. These are: *RDY*, *XRDY*, *INT**, *NMI**, *HOLD**, and *SIXTN**.

*SUXTN** is not implemented on the Big Z CPU. *SIXTN** is a 16-bit acknowledge signal indicating that a requested 16-bit data transfer is possible. Since the Big Z is an 8-bit oriented CPU, this signal is not required.

RDY is provided to the CPU from S-100 bus pin 72. This is a general ready line, and is specified as an open collector line. It is input to the CPU card from S-100 connector pin 72 and is routed to AND gate U7 where it is ANDed with *XRDY*. A pullup resistor on resistor pack U32 holds pin 2 of AND gate U7 normally high.

XRDY is provided to the CPU from S-100 bus pin 72. This is a special ready line commonly used by front panel devices to stop and single-step the processor. The IEEE does not specify it is an open collector line.

therefore it should not be used by other cards on the bus else a bus conflict may be created. XRDY is also routed to AND gate U7. A pullup resistor on resistor pack U31 holds pin 1 of AND gate U7 normally high.

A low on either input of U7 will result in a low output from pin 3. In other words, when either XRDY or RDY go false (low), the output of U7 will go low. The output of U7 (pin 3) is applied to input pin 12 of AND gate U7, where it is ANDed with the output of the wait-state generator U20, which is normally low unless a wait state is being generated. The output of U7, pin 11, is applied to the Z80 WAIT* input on pin 24 of the CPU. Therefore, a wait state is generated to the Z80 by either the wait state generator U20, or by XRDY or RDY being pulled low (going false) on the S-100 bus.

INT* and NMI* are input directly to the corresponding pins on the Z80 (pins 16 and 17, respectively), through input buffer U17. The tri-state inputs of U17 are grounded; therefore, the buffer is always enabled and these signals pass unimpeded through the buffer to the Z80 CPU.

These two lines are used to request service from the CPU. The INT* line may be masked by a Disable Interrupt command to the CPU, but the NMI* line is non-maskable and will always be responded to by the Z80. Both lines should be asserted as a level, rather than a pulse, and should be held true until the interrupt is acknowledged.

HOLD* is input to the CPU from S-100 bus pin 74, through buffer U17. The output of U17, pin 3, is routed directly to the BUSRQ* line on the Z80 CPU on pin 25. Buffer U17 is never tri-stated, since its tri-state inputs are grounded; therefore, the CPU will always respond to HOLD*.

HOLD* is specified as an open collector line and signals that a bus device is requesting the Z80 to relinquish the bus for a DMA operation.

HOLD*, NMI*, and INT* are held normally high by resistor pack U31 on the inputs of buffer U17.

Non-IEEE Control Lines

RFSH* is provided to the S-100 bus as the non-inverted RFSH* signal of the Z80 CPU. Z80 RFSH* on pin 28 of the CPU is routed to input pin 12 of buffer U6. It is transferred through the buffer, exits on pin 11, and is routed to S-100 bus pin 66. This signal is generated as a service to dynamic memory cards that utilize the Z80 RFSH* signal.

MRQ is provided to the S-100 bus as the inverted MRQ* signal of the Z80 CPU. Z80 MRQ*, on pin 19 of the CPU, is inverted by U18, and is applied to input pin 12 of buffer U17 as MRQ. It is transferred through the buffer, exits on output pin 11, and is routed to S-100 bus pin 65. This signal is generated as a service to memory and other cards that require the MRQ signal.

Both of the above signals utilize S-100 pins that have not been defined by the IEEE S-100 Standards Committee; therefore, there should be no conflict with IEEE S-100 standard cards.

pWAIT is provided to the S-100 bus as the inverted WAIT* signal going into pin 24 of the Z80 CPU. It is buffered by inverter U18, and is generated as a service to those cards that may require it. It, also, uses an IEEE undefined S-100 pin, pin 27.

DMA Control Lines

The primary DMA control lines utilized by the Big Z CPU card are: DODSB*, ADDSB*, STDSB*, and CCDSB*.

DODSB* comes into the Big Z CPU via pin 23 of the S-100 bus. It is routed through inverter U18, and is applied to the tri-state inputs of U37 and that portion of U25 which is concerned with the Data Out bus. The input side of inverter U18 is held normally high by pullup resistor R1. When DODSB* becomes true (low), the output of inverter U18 becomes high, disabling the data out buffers.

ADDSB* comes into the Big Z CPU via pin 22 of the S-100 bus. It is routed through inverter U18 (pins 1 and 2), and is applied to the tri-state inputs of U36, U35, and that portion of U25 which is concerned with the Address bus. The input side of inverter U18 is held normally high by a pullup resistor in resistor pack U31. When ADDSB* goes true (low), the output of inverter U18 will go high, disabling the address bus buffers.

STDSB* comes into the Big Z CPU via pin 18 of the S-100 bus. It is routed through inverter U30, and is applied to the tri-state inputs of U39. The input side of inverter U30 is held normally high by a pullup resistor in resistor pack U28. When STDSB* becomes true (low), the output of inverter U15 goes high and disables buffer U6, tri-stating pSYNC, pDBIN, sINTA, and pWR*.

The DMA arbitration lines DMA0* through DMA7* are not implemented on the Big Z CPU.

SYSTEM UTILITIES

System Power Lines

1. A positive 8 volt DC supply is assumed on S-100 pins 1 and 51. This supply is routed to voltage regulator VR4 where it is regulated to the plus 5 volts required by the chips on the board. A 1.5 microfarad tantalum capacitor is located on the input side of VR4, and a 0.1 microfarad ceramic capacitor is located at various places on the board, serving to bypass transients and helping to keep the plus 5 volt supply steady.

2. A negative 16 volt supply is assumed on S-100 bus pin 52. This supply is routed to voltage regulators VR1 and VR2, where it is regulated to the minus 12 volts and minus 5 volts required by the chips on the board. A

1.5 microfarad tantalum capacitor is located on both sides of both regulators, which serve to keep the voltage supply steady.

3. A positive 16 volt supply is assumed on S-100 bus pin 2. This supply is routed to VR3 where it is regulated to the plus 12 volts required by the chips on the board. In common with VR4, a 1.5 microfarad tantalum cap is located on the input side of VR3, and a 0.1 microfarad cap is located on the output side.

4. Ground lines are assumed on pins 50 and 100 of the S-100 bus. The Big Z CPU does not implement the ground lines on pins 20, 53, and 70 specified by the IEEE S-100 standard.

System Clock

The system clock, referred to on-board the Big Z CPU as Phi2, is generated by the Big Z oscillator section and is output to the S-100 bus on pin 24 through buffer U29.

Phi1 is also generated by the Big Z oscillator section and is output to the S-100 bus on pin 25 through buffer U29. **CAUTION:** Phi1 conflicts with the IEEE pSTVAL* signal line. In an IEEE system, this line must be cut. It is provided as a service to those cards that may require it. If no cards in your system require the Phi1 clock line, we suggest that this line should be cut.

The primary system clock is the Phi2 clock, which provides the control timing for all bus cycles.

CLOCK is derived from the Big Z oscillator section and is routed to the S-100 bus on pin 49, through buffer U29. It is a 2 MHz signal, regardless of the optional switch settings which select an internal 2 or 4 MHz clock. IEEE specifies a 2 MHz clock signal on this pin.

System Reset Functions

*RESET**. When *RESET**, coming into the Big Z CPU from S-100 bus pin 75, goes low (true), U11 provides a *RESET** signal to the Z80 CPU, and to the Power-On Latch. This signal is also provided to the S-100 bus as *POC** (Power-On Clear*) on S-100 pin 99. *RESET** and *POC** are held low for approximately 470 milliseconds due to the time it takes to recharge C22, a 100 microfarad electrolytic capacitor, through R3, a 4.7K ohm resistor. This meets the IEEE specification of a minimum active period of 10 milliseconds for *POC**

Memory Write Strobe

MWRT is provided to the S-100 bus on pin 68 via buffer U6. It is derived from the Z80 signals *MRQ** and *WR** true (active low on pins 19 and 22 of the Z80 chip), ANDed together by AND gate U17. When *WR** and *MRQ** on the Z80 are true, both inputs to AND gate U7 will be high, since the Z80 signals are inverted by inverter U18.

The generation of *MWRT* is inhibited when a front panel is connected to the system, and the front panel is

allowed to generate its own *MWRT* signal.

Special Caution

*SSWDSB** is provided to the Big Z CPU on S-100 bus pin 53. This signal is used as a sense-switch disable line on Imsai and other front panels. It is in direct conflict with IEEE S-100 standards, which define pin 53 as a ground line. If the Big Z CPU card is to be used with an IEEE S-100 system, or in an IEEE-standard motherboard, such as the JADE ISO-BUS, this line must be cut between pin 12 of NAND gate U22 and pin 53 of the S-100 bus. Since it is held normally high by the pullup resistor in resistor pack U31, cutting this line will not affect the normal operation of the CPU—it will merely allow it to run.

This concludes the Technical Description of the Big Z/S-100 interface. The following sections are a Technical Description of the EPROM interface, the USART interface, and the Oscillator sections of the board.

EPROM INTERFACE

The EPROM interface circuitry is comprised of DM8131 comparator U34, switch module U33, NAND gates U10, U22, and U4, inverter U15, and AND gate U7.

The comparator at U34 monitors the state of address lines A10 through A15 (depending on which EPROM you have selected) on the internal address bus. It compares the state of these lines to the settings of switch module U33. If a particular switch (1 through 7) of U33 is closed, the switch-side inputs to comparator U34 are grounded (low). If the switches are open, the switch-side inputs to comparator U34 are pulled high by pullup resistors in resistor pack U32.

When a state of equality exists between the switch settings and the current state of A10 through A15, the equal compare output at pin 9 of U34 will go low. This signal is always inverted by inverter U15; therefore, when the comparator finds equality, the output of U15 will be high. Conversely, when there is inequality, the output of U15 will be low.

The output of U15 is applied to input pin 9 of NAND gate U22, where it is NANDed with the output of AND gate U41, pin 6, defined as *MEMRD* (memory read). When equality is true (high at this point) and *MEMRD* is true, the output of NAND gate U22, pin 8, will be low; but if either *MEMRD* or equality is false (low), the output of U22 will be high.

NAND gates comprising two sections of U10 are connected as a flipflop whose SET input is at pin 13, and whose RESET input is at pin 9. This cross-connected set of NAND gates is referred to as the Power-On Jump/Reset Latch (hereafter referred to as the POJ Latch).

The RESET* signal, connected to RESET* pin 26 of the Z80 CPU, is connected to the SET input of the POJ latch through switch 8 of switch module U23. When this switch is closed, a negative pulse from the RESET* line will set the latch. The SET input of the POJ latch is held normally high by a pullup resistor in resistor pack U28.

Consider a power-on sequence: the state of comparator U34 may be indeterminate, but we know that RESET* will be low (true); therefore, a low pulse will be applied to pin 13 of U10. This results in a high output which is routed to pin 10, forcing pin 8 to go low. Now we have two lows on the inputs of 13 and 12 at U10, so the output on pin 11 will definitely be high. This circles around, like a dog chasing its own tail, reinforcing its own state and tending to keep the flipflop set. This high output is also applied to NAND gate U22 via input pin 5.

Since the first instruction the Z80 will execute is a memory read, MEMRD will also soon go high. This forces the output of NAND gate U22, pin 6, low. This low is applied to AND gate U7, which results in a low being output on pin 6, and the EPROM is selected (EPS* becomes true). Now the Z80 will begin reading its instructions from the EPROM. This state of affairs will continue until the EPROM jumps outside its own range.

EPS* can only be generated by one of the following conditions: The POJ latch is set, or there is a state of equality on the comparator and MEMRD is true. The first condition is met during reset; the second condition is met when we are doing memory reads in the address range selected by the switches on U33.

EPS* is applied to pin 4 of NAND gate U4. If EPS* is true (low), the output of U4 at pin 6 must be high; therefore, the data in buffers are disabled, and we can only read from the EPROM.

By the same token, if we are *not* reading from the EPROM, EPS* will be false (high). If we are reading from the USART, DCS* will be true (low), and again the output of U4 will go high, disabling the data in buffers. If EPS* is false (high), and DCS* is also false (high), there is yet another condition that can tri-state the data in buffers: SSWDSB* is true (low) at pin 53 of the S-100 bus (remember, we told you to cut it when the Big Z was used in a system where pin 53 is always grounded), or either RUN or SS is low (false) at pins 71 and 21 of the S-100 bus.

How does the EPROM get selected in the Shadow Mode? Simple. The address switches on U33 don't necessarily have anything to do with it. When the CPU is reset, the RESET* line at pin 13 of U10 will go low, forcing the output high and setting the POJ latch. The first instruction executed by the Z80 will be a read (op code fetch), so pin 4 of U22 goes high along with pin 5

(the SET condition of flipflop U10). This outputs a low to pin 5 of U7. The other side of this AND gate is held high by the pullup resistor R14, and since the J-K link is cut, it must remain high, irrespective of the state of the output of U22 pin 8, because there is nothing to pull it low. Therefore, a low on pin 5 of U7 ANDed with a high on pin 4 must result in a low being output from pin 6, which is—you guessed it—the EPS* signal. Since the address bus of the Z80 will be at zero, and we no longer care about the state of A10-A15, the Z80 must begin executing instructions from the EPROM.

Now, when MEMRD is true and we have an equality from the comparator, the POJ latch is reset and the EPROM is deselected, never to be heard from again and vanishing into thin air like a Hindu fakir. Why? Because the only thing that will *set* the POJ latch again is another reset or power-on condition. *Voila!* We are Shadowed.

Note that the Z80 can do memory *writes* to anywhere in memory, and all I/O operations, and even reads from memory as long as the address range from which it is reading is different from that selected by the switches of U33.

This circuitry is subtle, and not immediately apparent—but trust us, it works. A little pencil-and-paper doodling with logic equations will prove it to even the most stubborn doubter.

USART INTERFACE

The USART interface circuitry is comprised of comparator U24, switch module U23, pullup resistor pack U32, the baud rate generator and its associated crystal, OR gate U14, inverter U15, NOR gate U8, the USART itself (an 8251), and the RS232 level shifters at U12 and U9.

The lower portion of the internal address bus is monitored by the comparator U24 on lines A2-A7. The current state of the address bus is compared to the switch settings on U23 switches 1 through 6. As with the EPROM select circuitry, the switch-side inputs to the comparator can be either low or high—high if the switch is open by courtesy of resistor pack U32, or low by virtue of the fact that when a switch is closed it is grounded.

When equality is found, pin 9 of the comparator will go low. This signal is applied to pin 9 of OR gate U14, where it is ORed with the output of OR gate U14, pin 11. U14's section whose output is on pin 11 ORs A1 with IORQ*. DCS* is generated by an IORQ* true (low) or A1 low, ORed with equality from comparator U24. The output of U14 pin 8 is also applied to U4 pin 5 as DCS* to disable the data in buffers.

Tx and Rx clocks are provided to the USART via the MC14411 baud rate generator, whose internal timing is determined by Y2 crystal. A 16-times maximum baud

rate (9600 baud or 153.6 KHz) is provided by NOR gate U8. One input, pin 8, is grounded; the other is routed in from the baud rate generator U2 pin 18.

The Tx data output from the 8251 USART is sent to pin 2 of U12, an MC1488 RS232 level shifter, where it is output from pin 3 as a level that swings between plus and minus 12 volts.

Similarly, the Rx data input to the USART is sent from RS232 level shifter U9 to pin 3 of the USART, as is the Reverse Channel signal. Reverse Channel can be used as a "busy" or "not ready" indicator.

RxD, TxD and RVC are available at the front panel and USART connector U19 at pins 16, 12, and 14 respectively.

CAUTION: If you are using a front panel board connected to U19, make *sure* that it does not make contact with the USART side (pins 9-16). Failure to observe this caution can result in damaged front panel boards and damaged RS232 level shifters. Watch those Imsai front panels!

OSCILLATOR SECTION

The oscillator section of the Big Z CPU consists of the following components:

A. Main Oscillator Circuit

This consists of crystal Y1, a 4 MHz crystal; inverter U21 (2 sections), capacitors C23, 26 and 27 (0.001 microfarad caps); R10 and R11; and section 1 of U11, a 7474 flipflop. Pin 4 of U21 produces a 4 MHz square wave as the result of the action of the crystal, capacitors, resistors and inverters in the circuit. Flipflop U11 is connected as a divide-by-two circuit. Its Q output, on pin 5, is presented to pin 4 of buffer U29, where it is buffered out to pin 49 of the S-100 bus as CLOCK*. Its Q* output, on pin 6, reaches around to its D input, forming the divide-by-two, and is also presented to switch S1 as a 2 MHz signal.

Switch 1 chooses between the 4 MHz signal available from pin 4 of U21, or the 2 MHz signal available as the Q* of U11.

B. Secondary Oscillator Circuit

This circuit consists of switch 1, and sections of inverters U15, U21, and U30. The center point of the single-pole double-throw switch S1 receives either a 2 MHz square wave or a 4 MHz square wave, depending on its position. This is fed through inverter U21 (pins 5 and 6) to the Z80 Phi clock input on the CPU pin 6. It is also fed to input pin 13 of inverter U30, exits via pin 12, and is applied to input pin 2 of buffer U29. It passes through buffer U29 which is always enabled by virtue of the fact that its tri-state inputs are grounded, exits at pin 3, and is transmitted to the S-100 bus, pin 24, as the Phi2 clock.

The center point of switch S1 is additionally fed to pin 9 of inverter U21, where it is delayed by the gate-

time of U21, exits via pin 8, and is routed to input pin 13 of inverter U30 through an RC network consisting of C25, a 100 picofarad capacitor, and R12, a 6.8K ohm resistor. This RC network delays the signal by approximately 680 nanoseconds. At inverter U30, the signal is again slightly delayed by the inverter's gate time, exits on pin 10, and is routed to input pin 10 of buffer U29. It passes through the buffer, exits via pin 9, and is transmitted to the S-100 bus on pin 25 as Phi1 clock.

CAUTION:

Phi1 clock is provided as a convenience only, and is in direct conflict with the IEEE specification of pin 25 as pSTAVAl*. On IEEE S-100 systems, this clock should be eliminated by cutting the trace between U29 pin 9 and S-100 bus pin 25.

For those cards or systems that require the Phi1 clock signal, this circuitry provides a very good approximation of the actions of an 8080-style 8224 clock driver.

This concludes the Technical Description of the Big Z CPU.

THE BIG Z OPTIONS

OPTION 1—ON-BOARD EPROM

You should have installed the following components: an 8-position switch module at U33, a 24-pin socket at U13, a 16-pin socket at U34, and an 8131 IC at U34.

For a 2708-type EPROM

1. Set switch 7 on U33 to OFF.
2. Set switch 8 on U33 to ON.
3. Select EPROM address from Table A-1 and set the switches on U33 accordingly.

For a TMS 2716-type (TI three-voltage EPROM):

1. Install a jumper from A to C.
2. Install a jumper from D to B.
3. Cut the etch from B to C.
4. Set switches 1 and 7 on U33 to ON.
5. Set switch 8 on U33 to OFF.
6. Select EPROM address from Table A-2 and set the switches on U33 accordingly.

For an Intel-type 2716 (single plus 5 volt only)

1. Cut the etch from L to E.
2. Cut the etch from F to M.
3. Install a jumper from D to M.
4. Install a jumper from C to B.
5. Install a jumper from I to A.
6. Install a jumper from plus 5 volts to E.
7. Set switches 6 and 7 on U33 to ON.
8. Set switch 8 on U33 to ~~ON~~ OFF.
9. Select EPROM address from Table A-2 and set the switches on U33 accordingly.

For an Intel 2732/TMS 2732 (4K) EPROM:

1. Cut the etch from L to E.
2. Cut the etch from F to M.
3. Cut the etch from G to H.
4. Install a jumper from D to M.
5. Install a jumper from G to B.
5. Install a jumper from C to B.
6. Install a jumper from G to E.
7. Install a jumper from H to I.
8. Set switch 1, 2 and 7 on U33 to ON.
9. Set switch 8 of U33 to OFF.
10. Select EPROM address from Table A-3 and set the switches on U33 accordingly.

OPTION 2—M1 WAIT STATE

1. Set switch 7 of U23 to OFF.
2. Install a jumper from R to F.
3. Change USART option to Option 7.

OPTION 3—1K x 8 Masked ROM (VECTOR GRAPHIC MONITOR)

1. Install a jumper from I to A.
2. Set switch 1 on U33 to OFF.
3. Set switch 8 on U33 to ON.
4. Select EPROM address from Table A-1 and set switches on U33 accordingly.

OPTION 4—NO EPROM AND NO POWER-ON JUMP

1. Set switch 7 and 8 on U23 to OFF.

OPTION 5—POWER-ON JUMP

1. Set switch 8 on U23 to ON.

NOTE: an EPROM *must* be on the board to use the Power-On Jump Option. The Big Z CPU will not perform an off-board Power-On Jump.

OPTION 6—EPROM WAIT STATE (4MHz)

1. Set switch 7 on U23 to ON.

NOTE: An EPROM *must* be on the board to use this option.

OPTION 7—USART OPTION

You should have installed the following components: an 8-position switch module at U23, a 22 megohm resistor at R6, a 1.8432 MHz crystal at Y2, a 24-pin socket at U2, a 28-pin socket at U3, a 16-pin socket at U24, an 8131 IC at U24, an 8251 IC at U3, a MC14411 IC at U2, an MC1488/75188 IC at U12, a MC1489/75189 IC at U9, the plus and minus 12 volt regulators at VR3 and VR2 respectively, and an 8-position switch module at U1.

1. Set ONE switch on U1 to the desired baud rate. Note that only ONE switch may be on at any given time.

The baud rate is silk-screened next to U1 on the board. All switches other than the one selected must be set OFF.

2. Select the desired I/O port address from Table A-4 and set the switches on U23 accordingly.

OPTION 8—SHADOW EPROM

1. Cut the etch from J to K.
2. Install EPROM as shown in Option 1.
3. Enable the Power-On Jump as shown in Option 5.

This option is normally used to perform a system boot function. When the system is powered up or reset is activated, the power-on/reset latch formed by U10 is on and the processor will run code from the EPROM. The processor will continue running from the EPROM until a jump occurs to the address range selected by the switches on U33. Note that the program in the EPROM should be assembled to run in an address range OTHER than the one which is selected by the switch positions on U33.

When the jump to the selected U33 address range is detected, the EPROM will no longer be accessed, and will be transparent to the system. The program in the EPROM may be assembled to run in any address range as long as that address range is different from the range selected by the switches on U33. The EPROM is accessed for all memory read operations until a memory read is detected that generates an address in the range selected by the switches on U33. At this time, normal memory reads may take place because the power-on/reset latch will be cleared, and normal addressing is restored. I/O instructions and memory writes will execute normally while the power-on/reset latch is set, but all memory reads will address the EPROM.

OPTION 9—MRQ*

Please note that the Memory Request Strobe MREQ, as supplied to the S-100 bus by the Big Z CPU card is a *positive true* signal. This does not conform with many memory card requirements. If your memory cards require an MRQ* signal, you can invert MRQ by using one of the spare gates on the board. To do this, tie pins 9 and 10 of U4 high by installing a jumper between these pins and pin 14 (5 volts) of U4. Cut the etch that runs between pin 11 of U17 and pin 65 of the S-100 bus. Install a jumper from pin 11 of U17 to pin 11 of U4. Install a jumper from the output of U4, pin 8, to S-100 bus pin 65. This will give you an inverted MRQ signal. Although the timing of this signal will be slightly delayed, the delay is negligible and should meet the requirements of most any memory board.

BOARD ASSEMBLY INSTRUCTIONS

The **JADE BIG Z** CPU board is intended for those people who have had some prior experience with kit building and digital electronics. If you do not fall into this category, it is highly recommended that you find an experienced person to help you with the assembly and checkout of the board.

Although there is nothing sacred in the suggested steps that follow, if you will follow them step-by-step you should find your task much easier. We suggest that you start at a time when you will be able to complete the board. It will help to mark the boxes as you complete each step.

1. Make sure you have the tools you will need to assemble this kit. For this board you will need the following: a soldering iron (20 watts maximum), *Rosin Core* solder (preferably 63/37), diagonal cutters, a small magnifying glass, a screwdriver, and a lead former or a pair of needle-nose pliers.

2. Check the parts received against the parts list. Take special care to correctly identify look-alike parts; i.e., resistors, capacitors and diodes. If anything is missing from your kit, please call **JADE's** Customer Service Department and report the shortage immediately.

3. Read the section of this manual titled "Construction and Soldering Tips." If you have trouble identifying any of the parts, the section titled "Parts Identification" should help you. Do this *now* before you proceed any further.

CAUTION

USE EYE PROTECTION WHILE SOLDERING OR CUTTING WIRE

4. Install 14-pin sockets at U4, U5, U7, U8, U9, U10, U11, U12, U14, U15, U18, U20, U21, U22, U30, and U41. Do *not* solder them in yet.

5. Install 16-pin sockets at U6, U17, U24, U25, U26, U27, U28, U29, U31, U32, U34, U35, U36, U37, U38, U39, and U40. Do *not* solder them in yet.

6. Install 24-pin sockets at U2 and U13. Do *not* solder them in yet.

7. Install 28-pin socket at U3. Do *not* solder it in yet.

8. Install 40-pin socket at U16. Do *not* solder it in yet.

9. A handy trick to help you construct your board is to insert all the above sockets into the board first, then place the flat styrofoam cover you received with your kit box firmly against the top of the board. Turn it over, holding the flat styrofoam piece tightly against the board. The IC sockets should not be on the bottom. Press the board down, forcing the sockets into the styrofoam. Now solder alternating corner pins of the IC sockets to hold them in place temporarily (pins 8 and 16 on a 16-pin socket, for instance.)

Now turn the board over and very carefully inspect it to determine that all the IC sockets are down flat against the board. If you find any that aren't down flat, melt the solder joints at the corners of the IC socket and press it down against the board.

When you have determined that all the IC sockets are down firmly on the board, turn the board back over and solder all the pins. Make sure that all the pins are sticking through the board. IC sockets are very difficult to remove once they are soldered onto a board. For soldering hints, turn to Appendix B of this manual.

10. Install 1.5 ufd capacitors at C16 through C21. (NOTE that there are two C17s on the board. This is to allow you a choice between using dip tantalum caps and radial electrolytics. Dip tantalums are much preferable and are the type shipped with the Big Z kits as supplied by **JADE**. Install C17 according to the type of capacitor you are using.)

11. Install 0.1 ufd capacitors at C1 through C15.

12. Install the three DIP switches at U1, U23, and U33. Do not place these DIP switches in sockets—they are liable to fall out under use.

- 13. Install a 100 microfarad electrolytic capacitor at C22.
- 14. Install a 100 picofarad capacitor at C24 and C25.
- 15. Install a 0.001 ufd capacitor at C23, C26, and C27.
- 16. Install a 330 ohm resistor (orange, orange, brown) at R5.
- 17. Install the 1K ohm resistors (brown, black, red) at R4, R10, and R11.
- 18. Install a 2.7K ohm resistor (red, violet, red) at R2.
- 19. Install the 4.7K ohm resistors (yellow, violet, red) at R1, R3, R7, R8, R9, R13 and R14.
- 20. Install the 6.8K ohm resistors (blue, gray, red), at R12.
- 21. Install the 22 megohm resistor (red, red, blue) at R6.
- 22. Install a 4 MHz crystal at Y1.
- 23. Install a 1.8432 MHz crystal at Y2.
- 24. Install the voltage regulators. The 7805/LM340T5 regulator is installed at VR4. This is the plus 5 volt regulator and should be used with a heat sink. If you have a good heat sink compound, we suggest you use it at this regulator only. Use it sparingly, as too much is worse than none at all. Now install the 7912/LM320T12 regulator (minus 12 volts) at VR2. Install the 7905/LM320T5 (minus 5 volts) regulator at VR1. Install the 7812/LM340T12 (plus 12 volts) regulator at VR3. Button them down with the screws and nuts supplied. Place the screw through the

solder side of the board, with the nut next to the regulator.

- 25. Check all your solder joints carefully. Inspect the board for cold solder joints or solder bridges, as per the instructions in Appendix B.
- 26. **BEFORE INSTALLING ANY ICs**—place the board in your computer and check all the voltages to make sure that you do not have any power supply shorts on the board. The output voltages from all the regulators can be measured on the pin facing toward the top of the board (away from the S-100 connector). Be careful not to let your probes short the voltage regulator pins together, since this can destroy a voltage regulator very neatly—and quickly. If all of the voltages are up to par (plus or minus about half a volt or so), continue to step 27; otherwise, check the board again for shorts. Find that short before you install any ICs, and correct it.
- 27. Install all ICs and resistor packs in the locations shown on the Assembly Drawing.
- 28. Install whatever options you have chosen from the Options list.
- 29. Install a single-pole double-throw switch at T-U-V. If a switch has not been included in your kit, solder in the wire-wrap pins in its place. The center to top hole (T to U) selects a 2 MHz clock. The center to bottom hole (U to V) selects a 4 MHz clock. Regardless of the switch setting, the CLOCK* signal on pin 49 of the S-100 bus will be 2 MHz, as per IEEE specifications.
- 30. You should now be on the air. If you have trouble, go to the "Troubleshooting Tips" section of this manual for checkout procedures. If you don't—happy computing!

CHECKOUT PROCEDURES AND TROUBLESHOOTING TIPS

Before plugging the board into the system, do the following:

1. Carefully inspect the board for solder shorts or damaged components.
2. Insure that all ICs are out of their sockets at this point.
3. Install all options that are to be used in your system. Be especially careful when installing EPROM options, because your EPROM may be permanently damaged by improper jumper configurations. Five-volt-only EPROMS can be destroyed by the minus 5 and plus 12 volts supplied to the EPROM socket if the etches are not properly cut. Ohm them out before

installing the EPROM, or check the voltages at the proper socket pins.

Some confusion can exist for parts labeled 2716. Texas Instrument parts use plus 12 and minus five volts, while others (such as Intel), are five-volt-only types. The Texas Instrument TMS2516 is a five-volt-only part that is identical to the Intel 2716.

4. Plug the processor board into the bus with power OFF, being careful to line up pins 50 and 100 with the ground pins on the bus. If the board should somehow inadvertently become reversed in the S-100 connector, extensive damage could result when power is applied. In most mainframes, it is physically impossible to insert the card backwards—but some

people have managed to do it. It never hurts to make sure, and we'd rather insult your intelligence by telling you about it than see you destroy your CPU card.

5. It is highly recommended that the plus five volt supply be monitored while applying power for the first time. Shut the system down *immediately* if the supply does not read five volts (plus or minus something really reasonable). Monitor the other voltages as well before attempting to run the processor in the system.

6. Next, install all the ICs in their sockets according to the parts list or the assembly drawing. Make certain that pin one of all ICs are down, facing the S-100 bus connector on the board. There is no exception to this rule—all ICs face the bottom of the board. If you are not sure where pin 1 is on an IC, refer to the parts identification section of this manual.

7. Carefully turn the power on. Check for any discoloration in the parts and touch each IC gingerly. If it is *very* hot, chances are that you have inserted it backwards. Remove it, throw it away, and install a new part. The old one might work, but it is bound to fail in the near future, and according to Murphy's Law, which states that darn near anything can happen bad, it will fail exactly when you are most depending on it, like in a 14-hour sort or something. (Editor's Note: JADE's corollary to Murphy's Law states that "Murphy was an *optimist!*")

If you have a front panel, single-step the board to see if the first few instructions are fetched properly. In case of problems, carefully check all options installations and switch settings, since this is the most common cause of difficulty with this board.

Please note that not all front panel boards will work with the **Big Z** CPU card. Since the Big Z was designed to conform as much as possible with the proposed IEEE S-100 standard, it does not provide mirrored I/O addressing. Mirrored I/O addressing is an old Imsai/80890 convention in which the I/O address is mirrored (carried by both the upper and lower halves of the address bus). With the advent of the Z80 CPU, it became possible to perform block I/O instructions. The Z80 uses the upper half of the address bus to provide a byte count to its peripherals during these block move I/O instructions, and the use of mirrored I/O addressing effectively precludes this entire class of very useful instruction from the Z80's repertoire.

Some board designers (heaven only knows why) decode the upper half of the address bus for an I/O address. Why? We've never been able to figure it out. Among these that we know about are the Vector Graphic Flashwriters and I/O cards, Imsai front panel boards, Imsai I/O boards, the MECA tape system, Computime clock and calculator boards, and others.

Although the IEEE does not specifically forbid this practice, it is strongly discouraged. The designers of

the Big Z CPU have elected not to implement mirrored I/O addressing. If you have cards which use this addressing scheme, we suggest that they be modified to **decode the lower half of the address bus (A0-A7) rather than the upper half.**

One of the most common problems we have encountered with our customers using the Big Z is caused by the EPROM not being properly accessed after a power-on or reset. If the EPROM you are using has a paper label over the window, do not assume that it is a 2708 or other EPROM. Carefully lift the label to see if a transparent window is present on the device. If no window is present, it is a masked ROM or PROM. ROMs and PROMs that have pinouts similar to the 2708 or 2716 will work on the Big Z provided that you insure that pins 18, 19, 20 and 21 of the device are supplied with the same voltages as in the circuit in which they were originally used.

Instructions are included in the Options section for interfacing a Vector Graphics Monitor ROM. Note that the ROM, PROM or EPROM that is the starting point of the system monitor or bootstrap loader must be located on the Big Z CPU board in order to use the power-on jump feature. Devices that form the remainder of the system monitor may reside on other boards in the system, but the starting point of the monitor *must* be on the processor board.

Tarbell disk controllers that use an on-board cold-start loader ROM will not work with the Big Z. JADE has available several monitor ROMs that include the Tarbell disk interface cold-start loader routines. The on-board ROM on the Tarbell controller must be disabled.

To continue the checkout procedure:

8. If the voltages you have monitored during steps 5 and 7 have not been up to par, either the regulators are defective (most unlikely), or a short circuit exists somewhere on the board. Power down and check for solder bridges.

9. Check Z80 pin 6 for a 2 or 4 MHz square wave. If this is not present, you have trouble in the Oscillator section of the board. Check the ICs. Check the capacitors and resistors for proper values. Check for solder bridges or shorts.

10. Halt the CPU. Hold the reset button down and look at the following pins of the Z80 with a voltmeter or preferably a logic probe or oscilloscope:

pin 26 (RESET*) should be LOW.

pins 1-5 and 30-40 (A0-A15) should be HIGH.

pins 7-10 and 12-15 (D0-D7) should be HIGH.

Now release the RESET button. Look at the following pins on the Z80:

pin 26 (RESET*) should be HIGH.

pin 25 (BUSRQ*) should be HIGH.

pin 24 (WAIT*) should be LOW.
pin 18 (HLTA*) should be HIGH.
pin 27 (M1*) should be LOW.
pin 16 (INT*) should be HIGH.
pin 17 (NMI*) should be HIGH.
pin 23 (BUSAK*) should be HIGH.
A0-A15 should be LOW.

11. Install a monitor EPROM. Hit reset. Examine pin 9 of comparator U34. You should see a low-going pulse as the EPROM is selected. If pin 9 remains high, you have probably addressed your switches incorrectly. Check them out against the proper settings on the applicable Table A section for your type of EPROM. If pin 9 remains low, either there is something wrong with the address lines of the internal address bus, or the comparator is defective, or U10 is defective. Make sure you have the pullup resistor packs and pullup resistors properly installed.

12. With an EPROM installed, check pin 9 of comparator U24 to determine if the USART is being addressed correctly. Follow the same logic as in step 11 above.

13. Check your monitor program against the sample monitor program included with this manual. You may have a software problem. The most common software problem we have encountered centers around incorrect initialization of the 8251 USART.

PROGRAMMING THE USART

A simple program that uses the USART as output is included with this manual. Note that the RS232C interface from the USART is contained on the same DIP connector as the front panel signals. When connecting a front panel, be careful to insure that the RS232 levels do not go to any circuitry on the front panel through the DIP connector cable. This could render the USART unusable, as well as damage components on the front panel board. The DIP cable will have to be split at the DIP connector if a front panel is used in conjunction with the RS232 interface. A cable from pins 1 through 8 will go to the front panel. A cable from pins 9 through 16 will go to the RS232 connector or plug.

The USART appears as two consecutive port I/O addresses to the processor. U24 decodes a group of four consecutive addresses and the two lower addresses of this group of four are enabled by A1 going low at pin 12 of U14. The upper two addresses may be enabled to talk to the USART by cutting the etch on the solder side of the board at U14, pin 12.

An ODD address (i.e., A0 is 1 or high) selects the USART command/status register and an EVEN

address (i.e., A0 is 0 or low) selects the USART data register. After a power-on or reset, the USART must be programmed (initialized) for use by outputting a mode word, followed by a command word. The format for the mode word is as follows:

Bit 0 0

Bit 1 1

Bits 2 & 3:

00 means 5 bits per character.

10 means 6 bits per character.

01 means 7 bits per character.

11 means 8 bits per character (most usual configuration)

Bit 4—0 means parity disabled, 1 means parity enabled.

Bit 5—0 means odd parity selected, 1 means even parity selected.

Bits 6 & 7:

00 is an invalid, illegal combination.

01 means one and one-half stop bits.

10 means one stop bit (most usual configuration).

11 means 2 stop bits (usually used at 300 baud or less).

After writing the mode word, a slight delay is needed before writing the command word. This word can be sent to the USART after a LD A instruction, which will provide the necessary delay, and is required anyway. The command word is written to control the transmit or receive function of the USART. The functional format for the command word is as follows:

Initiate Transmit is 33 hex.

Initiate Receive is 36 hex.

Reset is 40 hex (same as a power-on condition).

Initiate both transmit and receive is 37 hex.

The mode and command words are only written *once* after a power-on or reset is performed. The command word may be written each time the function is to change or be selected. Note that this is not necessary when the command word sent to the USART is 37 hex—both transmit and receive are enabled.

The status register of the USART is obtained from inputting the command register. The format of the status register is as follows:

Bit 0. When this bit is high, it means that the Transmitter Buffer is empty and the USART is ready for another data character. This bit is reset by outputting a character to the USART's data register.

Bit 1. When this bit is high it means that a character has been received and assembled by the USART (data is available). This bit is reset when the character is

input from the data register of the USART.

Bit 2. When this bit is high, it means that the transmitter is enabled and the USART is in its Transmit Mode.

Bit 3. When this bit is high, it means that the USART has detected a parity error in the character it has just received, or transmitted.

Bit 4. When this bit is high, it signals an Overrun Error. This means that the received data was not input from the USART by the CPU soon enough to allow the USART to properly receive and assemble the next character.

Bit 5. When this bit is high, it signifies a Framing Error. A framing error means that an improper stop bit was detected at the end of the character. This condition can be caused by transmitting the wrong number of data bits or by the wrong baud rate being selected.

Bit 6 is not used, and its condition is meaningless.

Bit 7. When this bit is high, it means Reverse Channel. This is used for a "buffer full" or "not ready"

indication from peripheral devices. It can be active high or low, depending on the device. A TTL-level signal may be used at the RS232 interface if an RS232 signal is not available.

The following software example sets the mode word to select 8 bits per character, no parity, and 1 stop bit. The system should have been powered-on or reset just prior to executing this program. The command word that is output next selects the transmit and receive mode. The status is read and bit 0 is tested to see if the USART is ready for a character. If this bit is high, then a 55 hex (ASCII "U") is output as a character. The program then loops, testing the status, and transmits a continuous string of "U's". If the transmit data is viewed with an oscilloscope, it appears as a square wave with the low or high portions equal to the bit time or baud rate. The reciprocal of the baud rate will give the bit time in seconds. For example, 1/600 baud equals 1.667 milliseconds (0.001667 seconds).

USART SOFTWARE EXAMPLE

ADDR	CODE	STMT	SOURCE	STATEMENT
		0002	;	
		0003	PSECT	ABS
>0100		0004	ORG	0100H
		0005	;	
		0006	;	define symbols used
		0007	;	
>0011		0008	SSTAT	EQU 11H
>0010		0009	SDATA	EQU 10H
>0001		0010	TXRDY	EQU 01H
		0011	;	
		0012	;	
0100	3E4E	0013	PGM:	LD A,4EH ;mode word
0102	D311	0014		OUT (SSTAT),A
		0015	;	out to USART command port
0104	3E37	0016		LD A,37H ;command word
		0017	;	enables both transmit and receive
		0018	;	modes
0106	D311	0019		OUT (SSTAT),A
>0108		0020	LOOP:	
0108	DB11	0021		IN A,(SSTAT)
		0022	;	input from USART status port
010A	E601	0023		AND TXRDY
		0024	;	test for transmitter buffer ready
010C	28FA	0025		JR Z,LOOP-\$;loop until it's empty
010E	3E55	0026		LD A,55H ;ASCII "U"
0110	D310	0027		OUT (SDATA),A
		0028	;	transmit the character
0112	18F4	0029		JR LOOP-\$;return and do it again
		0030		END

EPROM TABLES

Table A-1

2704/2708 EPROM Address Select (U33)

Address Range	SW1 A15	SW2 A14	SW3 A13	SW4 A12	SW5 A11	SW6 A10
0000—03FFX	X	X	X	X	X	X
0400—07FFX	X	X	X	X	X	
0800—0BFFX	X	X	X	X		X
0C00—0FFFX	X	X	X	X		
1000—13FF	X	X	X		X	X
1400—17FF	X	X	X		X	
1800—1BFF	X	X	X			X
1C00—1FFF	X	X	X			
2000—23FF	X	X		X	X	X
2400—27FF	X	X		X	X	
2800—2BFF	X	X		X		X
2C00—2FFF	X	X		X		
3000—33FF	X	X			X	X
3400—37FF	X	X			X	
3800—3BFF	X	X				X
3C00—3FFF	X	X				
4000—43FF	X		X	X	X	X
4400—47FF	X		X	X	X	
4800—4BFF	X		X	X		X
4C00—4FFF	X		X	X		
5000—53FF	X		X		X	X
5400—57FF	X		X		X	
5800—5BFF	X		X			X
5C00—5FFF	X		X			
6000—63FF	X			X	X	X
6400—67FF	X			X	X	
6800—6BFF	X			X		X
6C00—6FFF	X			X		
7000—73FF	X				X	X
7400—77FF	X				X	
7800—7BFF	X					X
7C00—7FFF	X					
8000—83FF		X	X	X	X	X
8400—87FF		X	X	X	X	
8800—8BFF		X	X	X		X
8C00—8FFF		X	X	X		
9000—93FF		X	X		X	X
9400—97FF		X	X		X	
9800—9BFF		X	X			X
9C00—9FFF		X	X			
A000—A3FF		X		X	X	X
A400—A7FF		X		X	X	
A800—ABFF		X		X		X
AC00—AFFF		X		X		

Table A-1 (continued)

2704/2708 EPROM Address Select (U33)

Address Range	SW1 A15	SW2 A14	SW3 A13	SW4 A12	SW5 A11	SW6 A10
B000—B3FF		X			X	X
B400—B7FF		X			X	
B800—BBFF		X				X
BC00—BFFF		X				
C000—C3FF			X	X	X	X
C400—C7FF			X	X	X	
C800—CBFF			X	X		X
CC00—CFFF			X	X		
D000—D3FF			X		X	X
D400—D7FF			X		X	
D800—DBFF			X			X
DC00—DFFF			X			
E000—E3FF				X	X	X
E400—E7FF				X	X	
E800—EBFF				X		X
EC00—EFFF				X		
F000—F3FF					X	X
F400—F7FF					X	
F800—FBFF						X
FC00—FFFF						

Table A-2

2716/2516 EPROM Address Select (U33)

Address Range	SW1 A15	SW2 A14	SW3 A13	SW4 A12	SW5 A11
0000—07FF	X	X	X	X	X
0800—0FFF	X	X	X	X	
1000—17FF	X	X	X		X
1800—1FFF	X	X	X		
2000—27FF	X	X		X	X
2800—2FFF	X	X		X	
3000—37FF	X	X			X
3800—3FFF	X	X			
4000—47FF	X		X	X	X
4800—4FFF	X		X	X	
5000—57FF	X		X		X
5800—5FFF	X		X		
6000—67FF	X			X	X
6800—6FFF	X			X	
7000—77FF	X				X
7800—7FFF	X				
8000—87FF		X	X	X	X

Table A-2 (continued)

2716/2516 EPROM Address Select (U33)

Address Range	SW1 A15	SW2 A14	SW3 A13	SW4 A12	SW5 A11
8800—8FFF		X	X	X	
9000—97FF		X	X		X
9800—9FFF		X	X		
A000—A7FF		X		X	X
A800—AFFF		X		X	
B000—B7FF		X			X
B800—BFFF		X			
C000—C7FF			X	X	X
C800—CFFF			X	X	
D000—D7FF			X		X
D800—DFFF			X		
E000—E7FF				X	X
E800—EFFF				X	
F000—F7FF					X
F800—FFFF					

Table A-3

2732 EPROM Address Select (U33)

Address Range	SW1 A15	SW2 A14	SW3 A13	SW4 A12
0000—0FFF	X	X	X	X
1000—1FFF	X	X	X	
2000—2FFF	X	X		X
3000—3FFF	X	X		
4000—4FFF	X		X	X
5000—5FFF	X		X	
6000—6FFF	X			X
7000—7FFF	X			
8000—8FFF		X	X	X
9000—9FFF		X	X	
A000—AFFF		X		X
B000—BFFF		X		
C000—CFFF			X	X
D000—DFFF			X	
E000—EFFF				X
F000—FFFF				

Table A-4

USART Address Select (U23)

Address Range	SW1 A7	SW2 A6	SW3 A5	SW4 A4	SW5 A3	SW6 A2
00—01	X	X	X	X	X	X
04—05	X	X	X	X	X	
08—09	X	X	X	X		X
0C—0D	X	X	X	X		
10—11	X	X	X		X	X
14—15	X	X	X		X	
18—19	X	X	X			X
1C—1D	X	X	X			
20—21	X	X		X	X	X
24—25	X	X		X	X	
28—29	X	X		X		X
2C—2D	X	X		X		

Table A-4 (continued)

USART Address Select (U23)

Address Range	SW1 A7	SW2 A6	SW3 A5	SW4 A4	SW5 A3	SW6 A6
30—31	X	X			X	X
34—35	X	X			X	
38—39	X	X				X
3C—3D	X	X				
40—41	X		X	X	X	X
44—45	X		X	X	X	
48—49	X		X	X		X
4C—4D	X		X	X		
50—51	X		X		X	X
54—55	X		X		X	
58—59	X		X			X
5C—5D	X		X			
60—61	X			X	X	X
64—65	X			X	X	
68—69	X			X		X
6C—6D	X			X		
70—71	X				X	X
74—75	X				X	
78—79	X					X
7C—7D	X					
80—81		X	X	X	X	X
84—85		X	X	X	X	
88—89		X	X	X		X
8C—8D		X	X	X		
90—91		X	X		X	X
94—95		X	X		X	
98—99		X	X			X
9C—9D		X	X			
A0—A1		X		X	X	X
A4—A5		X		X	X	
A8—A9		X		X		X
AC—AD		X		X		
B0—B1		X			X	X
B4—B5		X			X	
B8—B9		X				X
BC—BD		X				
C0—C1			X	X	X	X
C4—C5			X	X	X	
C8—C9			X	X		X
CC—CD			X	X		
D0—D1			X		X	X
D4—D5			X		X	
D8—D9			X			X
DC—DD			X			
E0—E1				X	X	X
E4—E5				X	X	
E8—E9				X		X
EC—ED				X		
F0—F1					X	X
F4—F5					X	
F8—F9						X
FC—FD						

IEEE S-100 PINOUT
and
SIGNAL DEFINITIONS

The following S-100 pinout is as stated in the IEEE Preliminary Specifications, and is subject to revision.

- | | | |
|-----|----------|---|
| 1. | +8V | Average maximum must be less than 11 Volts. |
| 2. | +16V | Average maximum must be less than 21.5 Volts. |
| 3. | XRDY | Active high. One of two bus ready signals [see also pin 72]. |
| 4. | VIO* | Vectored Interrupt Line 0, active low, open collector. |
| 5. | VI1* | [see pin 4 above for this and the following:] |
| 6. | VI2* | |
| 7. | VI3* | |
| 8. | VI4* | |
| 9. | VI5* | |
| 10. | VI6* | |
| 11. | VI7* | |
| 12. | NMI* | Non-maskable Interrupt, active low, open collector. |
| 13. | PWRFAIL* | Active low bus power failure signal. |
| 14. | DMA3* | |
| 15. | A18 | Extended Address Bit 18 |
| 16. | A16 | Extended Address Bit 16 |
| 17. | A17 | Extended Address Bit 17 |
| 18. | SDSB* | Active low, open collector. Used to disable the 8 status signal lines. |
| 19. | CDSB* | Active low, open collector. Used to disable the 5 control output signals. |
| 20. | GND | Ground, common with pins 50 and 100. [Formerly defined as memory protect.] |
| 21. | NDEF | Not defined. Throughout this definition of the S-100 pinout, NDEF may be used by a manufacturer, but any pin so used must be fully specified. |
| 22. | ADSB* | Active low, open collector. Used to disable the 16 address lines. |
| 23. | DCDSB* | Active low, open collector. Used to disable the 8 data output lines. |
| 24. | Phi Clk | Phase 1 clock which provides the master timing for the bus. |
| 25. | #STVAL* | Status valid strobe, active low. In conjunction with #SYNC, this signal indicates that stable |

		address and status signals are present on the bus.
26.	#HLDA	Active high. Hold acknowledge signal.
27.	RFU	Reserved for future use.
28.	RFU	See above.
29.	A5	Address Bit 5
30.	A4	Address Bit 4
31.	A3	Address Bit 3
32.	A15	Address Bit 15
33.	A12	Address Bit 12
34.	A9	Address Bit 9
35.	DO1	Data Out Bit 1, bidirectional data bit 1
36.	DO0	Data Out Bit 0, bidirectional data bit 0
37.	A10	Address Bit 10
38.	DO4	Data Out Bit 4, bidirectional data bit 4
39.	DO5	Data Out Bit 5, bidirectional data bit 5
40.	DO6	Data Out Bit 6, bidirectional data bit 6
41.	DI2	Data In Bit 2, bidirectional data bit 10
42.	DI3	Data In Bit 3, bidirectional data bit 11
43.	DI7	Data In Bit 7, bidirectional data bit 15
44.	sM1	Status signal indicating that the current machine cycle is an op code fetch cycle.
45.	sOUT	Status signal indicating that the current machine cycle is an I/O output cycle.
46.	sINP	Status signal indicating that the current machine cycle is an I/O input cycle.
47.	sMEMR	Status signal indicating that the current machine cycle is a memory read cycle, and is not an INTA instruction fetch cycle.
48.	sHLTA	Status signal indicating that a HALT instruction is being executed.
49.	CLOCK	A 2 MHz [$\pm 0.5\%$], 40-60% duty cycle clock which is not required to be synchronous with any other bus signal.
50.	GND	Common with pin 100.
51.	+8V	Common with pin 1.
52.	-16V	
53.	GND	Common with pin 100. [Formerly Sense Switch Disable*. All CPU cards used in the IEEE S-100 bus which have the SSWDSB* line connected must have this pin cut. The signal may be connected through the front panel connector cable.]
54.	SLAVE CLR*	This is a signal used to reset bus slaves. It must be active with POC* and may also be generated by external means.
55.	DMA0*	Active low, open collector DMA request line.
56.	DMA1*	See above.
57.	DMA2*	See above.
58.	sXTRQ*	An active low status signal which requests 16-bit bus slaves to assert SIXTN*
59.	A19	Extended Address Bit 19
60.	SIXTN*	An active low status signal asserted by 16-bit bus slaves in response to sXTRQ*.
61.	A20	Extended Address Bit 20.
62.	A21	Extended Address Bit 21.
63.	A22	Extended Address Bit 22.

64.	A23	Extended Address Bit 23.
65.	NDEF	Not defined.
66.	NDEF	Not defined.
67.	PHANTOM*	Active low, open collector.
68.	MWRT	$\overline{\text{PWR}}^{\wedge}\text{sOUT}^*$, follows $\overline{\text{PWR}}^*$ within 30 ns.
69.	RFU	Reserved for future use.
70.	GND	Common with pin 100. [Formerly memory unprotect.]
71.	RFU	
72.	RDY	Active high, open collector [see comments for pin 3].
73.	INT*	Active low, open collector, principal interrupt request signal.
74.	HOLD*	Active low, open collector, used in conjunction with $\overline{\text{HLDA}}$ to coordinate DMA operations.
75.	RESET*	Active low, open collector, master reset signal.
76.	$\overline{\text{PSYNC}}$	Control signal identifying the beginning of a new bus cycle.
77.	$\overline{\text{PWR}}^*$	Active low control signal that identifies the presence of valid data on the DO bus.
78.	$\overline{\text{PDBIN}}$	Control signal requesting data on the DI bus.
79.	A0	Address Bit 0.
80.	A1	Address Bit 1.
81.	A2	Address Bit 2.
82.	A6	Address Bit 6.
83.	A7	Address Bit 7.
84.	A8	Address Bit 8.
85.	A13	Address Bit 13.
86.	A14	Address Bit 14.
87.	A11	Address Bit 11.
88.	DO2	Data Out Bit 2, bidirectional data bit 2.
89.	DO3	Data Out Bit 3, bidirectional data bit 3.
90.	DO7	Data Out Bit 7, bidirectional data bit 7.
91.	DI4	Data In Bit 4, bidirectional data bit 12.
92.	DI5	Data In Bit 5, bidirectional data bit 13.
93.	DI6	Data In Bit 6, bidirectional data bit 14.
94.	DI1	Data In Bit 1, bidirectional data bit 9.
95.	DI0	Data In Bit 0, bidirectional data bit 8.
96.	$\overline{\text{sINTA}}$	Status signal identifying a bus input cycle that follows an accepted interrupt request on INT*.
97.	$\overline{\text{sWO}}^*$	Active low status signal identifying a bus cycle which transfers data from a bus master to a bus slave.
98.	ERROR*	Active low, open collector status signal which identifies an error condition during the present bus cycle.
99.	POC*	Power-on clear signal for all bus devices. This signal, when asserted, must remain low for at least 10 milliseconds.
100.	GND	System ground line.

ADDR	CODE	STMT	SOURCE	STATEMENT
		0002	;	*****
		0003	;	*****
		0004	;	*** BIG Z MONITOR (1K VERSION 2.0) 9/10/79 AB
		0005	;	*****
		0006	;	ASSUMPTIONS
		0007	;	SERIAL PORT ON BIGZ IS SET TO 10 AND 11 HEX
		0008	;	TARBELL TAPE USING STANDARD TARBELL PORTS
		0009	;	OR KC STANDARD VIA JADE SERIAL/PARALLEL CARD
		0010	;	SET TO PORTS 01 & 81 HEX
		0011	;	NO MEMORY SIZE IS ASSUMED
		0012	;	
		0013	;	CONDITIONAL ASSEMBLY PARAMETERS
		0014	;	define values of true/false
>FFFF		0015	TRUE	EQU OFFFH
>0000		0016	FALSE	EQU 0
		0017	;	
		0018	;	set conditional assembly values
>0000		0019	TARBEL	EQU FALSE
>FFFF		0020	KCTAPE	EQU TRUE
		0021	;	
		0022	;	SYSTEM EQUATES
		0023	;	
		0024		PSECT ABS
>E000		0025	MON	ORG 0E000H
		0026	;	
>0000		0027	TAPE	EQU 0
>0080		0028	TAPST	EQU 80H
>0011		0029	KBDST	EQU 11H
>0010		0030	KBDDT	EQU 10H
>0002		0031	KBDIN	EQU 02H
>0001		0032	KBDOT	EQU 01H
>00FC		0033	WAIT	EQU 0FCH
>00FA		0034	SECT	EQU 0FAH
>00F8		0035	DCOM	EQU 0F8H
>00FB		0036	DDATA	EQU 0FBH
>00F8		0037	DSTAT	EQU 0F8H
>007D		0038	SB00T	EQU 007DH
>006E		0039	TARBL	EQU 6EH
		0040	;	
		0041	;	
E000	C321E0	0042		JP INIT
E003	C370E0	0043		JP EXEC
E006	C390E3	0044		JP CONIN
E009	C385E3	0045		JP CONOUT
E00C	C325E3	0046		JP HEXIN
E00F	C359E3	0047		JP HEXOUT
E012	C354E3	0048		JP DHXOT
E015	C370E3	0049		JP CRLF
E018	C37DE3	0050		JP SPACE
E01B	C32BE2	0051		JP TREAD
E01E	C395E2	0052		JP TWRT
E021	0601	0053	INIT	LD B,1
E023	3E4E	0054		LD A,4EH
E025	D311	0055		OUT (KBDST),A
E027	3E37	0056		LD A,37H
E029	D311	0057		OUT (KBDST),A
E02B	21FFFF	0058		LD HL,0FFFFH
E02E	23	0059	FTOP:	INC HL

```

      'BIG Z MONITOR 2.0.A/B'          SD SYSTEMS Z80 ASSEMBLER PAGE 0002
ADDR  CODE      STMT SOURCE STATEMENT

E02F  7E        0060          LD      A,(HL)
E030  2F        0061          CPL
E031  77        0062          LD      (HL),A
E032  BE        0063          CP      (HL)
E033  2F        0064          CPL
E034  77        0065          LD      (HL),A
E035  2004      0066          JR      NZ,FTOP1-*
E037  0600      0067          LD      B,0
E039  18F3      0068          JR      FTOP-*
E03B  78        0069 FTOP1: LD      A,B
E03C  B7        0070          OR      A
E03D  20EF      0071          JR      NZ,FTOP-*
E03F  2B        0072          DEC     HL
E040  2B        0073          DEC     HL
E041  F9        0074          LD      SP,HL
E042  E5        0075          PUSH   HL
E043  FDE1      0076          POP    IY
      0077 ;2 CR/LF's
E045  CD70E3    0078          CALL   CRLF
E048  CD70E3    0079          CALL   CRLF
E04B  2163E0    0080 FTOP2: LD      HL,MSG1
E04E  7E        0081 INIT1: LD      A,(HL)
E04F  CD85E3    0082          CALL   CONOUT
E052  23        0083          INC     HL
E053  FE03      0084          CP      03H
E055  20F7      0085          JR      NZ,INIT1-*
E057  CD70E3    0086          CALL   CRLF
E05A  210100    0087          LD      HL,1
E05D  39        0088          ADD     HL,SP
E05E  CD54E3    0089          CALL   DHXOT
E061  182D      0090          JR      EXEC-*
      0091          IF     TARBEL
      0092 MSG1: DEFM   'JADE COMPUTER SYSTEMS BIG Z MONITOR 2.0B'
      0093          ENDIF
      0094          IF     KCTAPE
E063  4A414445  0095 MSG1: DEFM   'JADE COMPUTER SYSTEMS BIG Z MONITOR 2.0A'
      20434F4D
      50555445
      52205359
      5354454D
      53204249
      4D4F4E49
      544F5220
      322E4F41
      0096          ENDIF
E08B  0D0A0D0A  0097          DEFB   0DH,0AH,0DH,0AH
E08F  03        0098          DEFB   03H
E090  FDF?      0099 EXEC: LD      SP,IY
      0100          IF     TARBEL
      0101          SUB     A
      0102          OUT   (TARBL),A
      0103          ENDIF
E092  CD70E3    0104 EXEC3: CALL   CRLF
E095  3E23      0105          LD      A,'#'
E097  CD85E3    0106          CALL   CONOUT
E09A  CD7DE3    0107          CALL   SPACE
E09D  CD90E3    0108 EXEC4: CALL   CONIN

```

ADDR	CODE	STMT	SOURCE STATEMENT
E0A0	FE21	0109	CP 21H
E0A2	FA9DE0	0110	JP M,EXEC4
E0A5	FE41	0111	CP 'A'
E0A7	284A	0112	JR Z,ALTER-\$
E0A9	FE44	0113	CP 'D'
E0AB	2871	0114	JR Z,DUMP-\$
E0AD	FE47	0115	CP 'G'
E0AF	283E	0116	JR Z,GO-\$
E0B1	FE43	0117	CP 'C'
E0B3	CAB8E1	0118	JP Z,COPY
E0B6	FE54	0119	CP 'T'
E0B8	CACDE1	0120	JP Z,TEST
E0BB	FE46	0121	CP 'F'
E0BD	CAA0E1	0122	JP Z,FILL
E0C0	FE4D	0123	CP 'M'
E0C2	CA3CE1	0124	JP Z,MAP
E0C5	FE4C	0125	CP 'L'
E0C7	CA72E1	0126	JP Z,LOAD
E0CA	FE53	0127	CP 'S'
E0CC	CA8CE2	0128	JP Z,TSAVE
E0CF	FE52	0129	CP 'R'
E0D1	CA17E2	0130	JP Z,TLOAD
E0D4	FE56	0131	CP 'V'
E0D6	CADEE2	0132	JP Z,VERIFY
E0D9	FE58	0133	CP 'X'
E0DB	CACBE2	0134	JP Z,STRM
		0135	IF KCTAPE
E0DE	FE59	0136	CP 'Y'
E0E0	CA68E2	0137	JP Z,TUNE
		0138	ENDIF
E0E3	FE42	0139	CP 'B'
E0E5	CAB5E3	0140	JP Z,BOOT
E0E8	FE45	0141	CP 'E'
E0EA	CA00F0	0142	JP Z,0F000H
		0143 :	the above is a jump to the Versafloppy BIOS ROM
E0ED	18A3	0144	JR EXEC3-\$
E0EF	CD22E3	0145 GO:	CALL SPHIN
E0F2	E9	0146	JP (HL)
E0F3	CD22E3	0147 ALTER:	CALL SPHIN
E0F6	CD70E3	0148 ALT1:	CALL CRLF
E0F9	CD54E3	0149	CALL DHXOT
E0FC	CD7DE3	0150	CALL SPACE
E0FF	7E	0151	LD A,(HL)
E100	CD59E3	0152	CALL HEXOUT
E103	E5	0153	PUSH HL
E104	CD22E3	0154	CALL SPHIN
E107	5D	0155	LD E,L
E108	E1	0156	POP HL
E109	FE0D	0157	CP 0DH
E10B	CA1BE1	0158	JP Z,ALT3
E10E	FE2F	0159	CP '/'
E110	CA90E0	0160	JP Z,EXEC
E113	FE2E	0161	CP '.'
E115	2001	0162	JR NZ,ALT2-\$
E117	73	0163	LD (HL),E
E118	23	0164 ALT2:	INC HL
E119	18DB	0165	JR ALT1-\$
E11B	2B	0166 ALT3:	DEC HL

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      'BIG Z MONITOR 2.0.A/B'          SD SYSTEMS Z80 ASSEMBLER PAGE 0004
ADDR  CODE      STMT SOURCE STATEMENT
E11C  18D8      0167          JR      ALT1-$
E11E  CD16E3    0168 DUMP:   CALL    DHXIN
E121  CD70E3    0169 DUMP1:  CALL    CRLF
E124  CD54E3    0170          CALL    DHXOT
E127  0610      0171          LD      B,16
E129  CD7DE3    0172 DUMP2:  CALL    SPACE
E12C  7E        0173          LD      A,(HL)
E12D  CD59E3    0174          CALL    HEXOUT
E130  CD06E3    0175          CALL    CMPDH
E133  DA90E0    0176          JP      C,EXEC
E136  23        0177          INC     HL
E137  05        0178          DEC     B
E138  20EF      0179          JR      NZ,DUMP2-$
E13A  18E5      0180          JR      DUMP1-$
E13C  0601      0181 MAP:    LD      B,1
E13E  210000    0182          LD      HL,0
E141  7E        0183 MAP1   LD      A,(HL)
E142  2F        0184          CPL
E143  77        0185          LD      (HL),A
E144  BE        0186          CP      (HL)
E145  2F        0187          CPL
E146  77        0188          LD      (HL),A
E147  3E00      0189          LD      A,0
E149  2801      0190          JR      Z,MAP2-$
E14B  3C        0191          INC     A
E14C  B8        0192 MAP2:  CP      B
E14D  47        0193          LD      B,A
E14E  2811      0194          JR      Z,MAP4-$
E150  2B        0195          DEC     HL
E151  B7        0196          OR      A
E152  2004      0197          JR      NZ,MAP3-$
E154  23        0198          INC     HL
E155  CD70E3    0199          CALL    CRLF
E158  CD54E3    0200 MAP3:  CALL    DHXOT
E15B  CD7DE3    0201          CALL    SPACE
E15E  2801      0202          JR      Z,MAP4-$
E160  23        0203          INC     HL
E161  23        0204 MAP4:  INC     HL
E162  7D        0205          LD      A,L
E163  B4        0206          OR      H
E164  20DB      0207          JR      NZ,MAP1-$
E166  78        0208          LD      A,B
E167  B7        0209          OR      A
E168  C290E0    0210          JP      NZ,EXEC
E16B  2B        0211          DEC     HL
E16C  CD54E3    0212          CALL    DHXOT
E16F  C390E0    0213          JP      EXEC
E172  CD7DE3    0214 LOAD:  CALL    SPACE
E175  CD8EE1    0215 LOAD0: CALL    LHXIN
E178  20FB      0216          JR      NZ,LOAD0-$
E17A  CD8EE1    0217 LOAD1: CALL    LHXIN
E17D  FE20      0218          CP      /
E17F  20F4      0219          JR      NZ,LOAD0-$
E181  EB        0220          EX      DE,HL
E182  CD8EE1    0221 LOAD2: CALL    LHXIN
E185  F5        0222          PUSH   AF
E186  7D        0223          LD      A,L
E187  12        0224          LD      (DE),A

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ADDR	CODE	STMT	SOURCE	STATEMENT
E188	13	0225		INC DE
E189	F1	0226		POP AF
E18A	20F6	0227		JR NZ,LOAD2-\$
E18C	18EC	0228		JR LOAD1-\$
E18E	CD25E3	0229	LHXIN:	CALL HEXIN
E191	FE0A	0230		CP OAH
E193	28F9	0231		JR Z,LHXIN-\$
E195	B7	0232		OR A
E196	28F6	0233		JR Z,LHXIN-\$
E198	FE23	0234		CP '#'
E19A	CA90E0	0235		JP Z,EXEC
E19D	FE0D	0236		CP ODH
E19F	C9	0237		RET
E1A0	CD16E3	0238	FILL:	CALL DHXIN
E1A3	D60D	0239		SUB ODH
E1A5	2806	0240		JR Z,FILLO-\$
E1A7	E5	0241		PUSH HL
E1A8	CD25E3	0242		CALL HEXIN
E1AB	7D	0243		LD A,L
E1AC	E1	0244		POP HL
E1AD	2B	0245	FILLO:	DEC HL
E1AE	23	0246	FILL1:	INC HL
E1AF	77	0247		LD (HL),A
E1B0	CD06E3	0248		CALL CMPDH
E1B3	30F7	0249		JR NC,FILL1-\$
E1B5	C390E0	0250		JP EXEC
E1B8	CD45E3	0251	COPY:	CALL TRPIN
E1BB	CD01E1	0252		CALL COPY0
E1BE	C390E0	0253		JP EXEC
E1C1	1B	0254	COPY0:	DEC DE
E1C2	0B	0255		DEC BC
E1C3	13	0256	COPY1:	INC DE
E1C4	03	0257		INC BC
E1C5	12	0258		LD (DE),A
E1C6	0A	0259		LD A,(BC)
E1C7	CD06E3	0260		CALL CMPDH
E1CA	30F7	0261		JR NC,COPY1-\$
E1CC	C9	0262		RET
E1CD	CD16E3	0263	TEST:	CALL DHXIN
E1D0	13	0264		INC DE ;add 1 to ending address
E1D1	E5	0265		PUSH HL
E1D2	DDE1	0266		POP IX ;save starting address
E1D4	0E00	0267		LD C,256 ;total number of passes
E1D6	0600	0268		LD B,0 ;starting pattern
E1D8	DDE5	0269	TEST0:	PUSH IX
E1DA	E1	0270		POP HL ;set preserved start address
E1DB	7D	0271	TEST1:	LD A,L
E1DC	AC	0272		XOR H
E1DD	A8	0273		XOR B
E1DE	77	0274		LD (HL),A
E1DF	23	0275		INC HL
E1E0	7C	0276		LD A,H
E1E1	BA	0277		CP D
E1E2	20F7	0278		JR NZ,TEST1-\$
E1E4	DDE5	0279		PUSH IX
E1E6	E1	0280		POP HL ;fetch start address for read test
E1E7	7D	0281	TEST2:	LD A,L
E1E8	AC	0282		XOR H

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      'BIG Z MONITOR 2.0.A/B'          SD SYSTEMS Z80 ASSEMBLER PAGE 0006
ADDR  CODE      STMT SOURCE STATEMENT

E1E9  A8          0283          XOR      B
E1EA  BE          0284          CP        (HL)
E1EB  C4FFE1      0285          CALL     NZ,ERRO ;found an error, exit
E1EE  23          0286          INC      HL
E1EF  7C          0287          LD       A,H
E1F0  BA          0288          CP        D
E1F1  20F4        0287          JR       NZ,TEST2-*
E1F3  04          0290          INC      B
E1F4  3E50        0291          LD       A,'P'
E1F6  CD85E3      0292          CALL     CONOUT
E1F9  0D          0293          DEC      C
E1FA  20DC        0294          JR       NZ,TEST0-*
E1FC  C390E0      0295          JP       EXEC
E1FF  F5          0296  ERRO:  PUSH     AF
E200  E5          0297          PUSH     HL
E201  CD54E3      0298          CALL     DHXOT
E204  CD7DE3      0299          CALL     SPACE
E207  78          0300          LD       A,B
E208  CD59E3      0301          CALL     HEXOUT
E20B  CD7DE3      0302          CALL     SPACE
E20E  F1          0303          POP      AF
E20F  CD59E3      0304          CALL     HEXOUT
E212  CD70E3      0305          CALL     CRLF
E215  E1          0306          POP      HL
E216  C9          0307          RET

      0308 ;
      0309 ;
      0310
E217  CD16E3      0311  TLOAD:  IF      KCTAPE
E21A  CD2BE2      0312          CALL     DHXIN
E21D  CA90E0      0313          JP       Z,EXEC
E220  CD7DE3      0314          CALL     SPACE
E223  3E23        0315          LD       A,'*'
E225  CD85E3      0316          CALL     CONOUT
E228  C390E0      0317          JP       EXEC
E22B  3EB0        0318  TREAD:  LD       A,0B0H
E22D  D380        0317          OUT      (TAPST),A
E22F  0604        0320  TRDA:  LD       B,4
E231  CD5FE2      0321  TRDB:  CALL     CIN
E234  FEFF        0322          CP        OFFH
E236  20F7        0323          JR       NZ,TRDA-*
E238  0B          0324          DEC      BC
E239  20F6        0325          JR       NZ,TRDB-*
E23B  CD5FE2      0326  TRDC:  CALL     CIN
E23E  FEFF        0327          CP        OFFH
E240  28ED        0328          JR       Z,TRDA-*
E242  FEE6        0329          CP        0E6H
E244  20E9        0330          JR       NZ,TRDA-*
E246  0600        0331          LD       B,0
E248  3E24        0332          LD       A,'*'
E24A  CD85E3      0333          CALL     CONOUT
E24D  2B          0334          DEC      HL
E24E  23          0335  TRD1:  INC      HL
E24F  CD5FE2      0336          CALL     CIN
E252  77          0337          LD       (HL),A
E253  80          0338          ADD     A,B
E254  47          0339          LD       B,A
E255  CD06E3      0340          CALL     CMPDH

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ADDR	CODE	STMT	SOURCE	STATEMENT
E258	30F4	0341	JR	NC, TRD1-\$
E25A	CD5FE2	0342	CALL	CIN
E25D	B8	0343	CP	B
E25E	C9	0344	RET	
E25F	DB80	0345	CIN: IN	A, (TAPST)
E261	E601	0346	AND	01H
E263	28FA	0347	JR	Z, CIN-\$
E265	DB00	0348	IN	A, (TAPE)
E267	C9	0349	RET	
E268	CD7DE3	0350	TUNE: CALL	SPACE
E26B	3EB0	0351	LD	A, OBOH
E26D	D380	0352	OUT	(TAPST), A
E26F	CD70E3	0353	TUN0: CALL	CRLF
E272	2620	0354	LD	H, 32
>E274		0355	TUN1:	
E274	CD5FE2	0356	TUN2: CALL	CIN
E277	FEFF	0357	CP	OFFH
E279	28F9	0358	JR	Z, TUN2-\$
E27B	2E2B	0359	LD	L, '+'
E27D	FEE6	0360	CP	OE6H
E27F	2802	0361	JR	Z, TUN3-\$
E281	2E3F	0362	LD	L, '?'
E283	7D	0363	TUN3: LD	A, L
E284	CD85E3	0364	CALL	CONOUT
E287	25	0365	DEC	H
E288	20EA	0366	JR	NZ, TUN1-\$
E28A	18E3	0367	JR	TUN0-\$
E28C	CD14E3	0368	TSAVE: CALL	DHXIN
E28F	CD75E2	0369	CALL	TWRIT
E292	C390E0	0370	JP	EXEC
E295	3EB0	0371	TWRIT: LD	A, OBOH
E297	D380	0372	OUT	(TAPST), A
E299	0610	0373	LD	B, 16
E29B	3EFF	0374	TWRTO: LD	A, OFFH
E29D	CDC0E2	0375	CALL	COUT
E2A0	05	0376	DEC	B
E2A1	20F8	0377	JR	NZ, TWRTO-\$
E2A3	3EE6	0378	LD	A, OE6H
E2A5	CDC0E2	0379	CALL	COUT
E2A8	2B	0380	DEC	HL
E2A9	0300	0381	LD	B, 0
E2AB	23	0382	TWRT1: INC	HL
E2AC	7E	0383	LD	A, (HL)
E2AD	CDC0E2	0384	CALL	COUT
E2B0	80	0385	ADD	A, B
E2B1	47	0386	LD	B, A
E2B2	CD05E3	0387	CALL	CMPDH
E2B5	30F4	0388	JR	NC, TWRT1-\$
E2B7	78	0389	LD	A, B
E2B8	CDC0E2	0390	CALL	COUT
E2BB	CDC0E2	0391	CALL	COUT
E2BE	1800	0392	JR	COUT-\$
E2C0	F5	0393	COUT: PUSH	AF
E2C1	DB80	0394	IN	A, (TAPST)
E2C3	E680	0395	AND	80H
E2C5	28FA	0396	JR	Z, COUT+1-\$
E2C7	F1	0397	POP	AF
E2C8	D300	0398	OUT	(TAPE), A

ADDR	CODE	STMT	SOURCE	STATEMENT
E2CA	C7	0399		RET
E2CB	CD7DE3	0400	STRM:	CALL SPACE
E2CE	3EB0	0401		LD A,0B0H
E2D0	D380	0402		OUT (TAPST),A
E2D2	3EFF	0403	STRM1:	LD A,OFFH
E2D4	CDC0E2	0404		CALL COUT
E2D7	3EE6	0405		LD A,0E6H
E2D9	CDC0E2	0406		CALL COUT
E2DC	18F4	0407		JR STRM1-*
		0408		ENDIF
		0409	;	
		0410		IF TARBEL
		0411	TLOAD	CALL DHXIN
		0412		CALL TREAD
		0413		JP Z,EXEC
		0414		LD A,'*'
		0415		CALL CONOUT
		0416		JP EXEC
		0417	TREAD	LD A,1
		0418		OUT (TARBL),A
		0419		PUSH HL
		0420		LD HL,20000
		0421		CALL DELAY
		0422		POP HL
		0423		LD B,0
		0424		LD A,11H
		0425		OUT (TARBL),A
		0426		DEC HL
		0427	TRD1	INC HL
		0428		CALL CIN
		0429		LD (HL),A
		0430		ADD A,B
		0431		LD B,A
		0432		CALL CMPDH
		0433		JR NC,TRD1-*
		0434		CALL CIN
		0435		CP B
		0436		PUSH AF
		0437		SUB A
		0438		OUT (TARBL),A
		0439		POP AF
		0440		RET
		0441	CIN	IN A,(TARBL)
		0442		AND 10H
		0443		JR NZ,CIN-*
		0444		IN A,(TARBL+1)
		0445		RET
		0446	TSAVE	CALL DHXIN
		0447		CALL TWRIT
		0448		JP EXEC
		0449	TWRIT	LD A,2
		0450		OUT (TARBL),A
		0451		PUSH HL
		0452		LD HL,OFFFH
		0453		CALL DELAY
		0454		POP HL
		0455		SUB A
		0456		LD B,A

ADDR	CODE	STMT	SOURCE	STATEMENT
		0457		CALL COUT
		0458		LD A,0E6H
		0459		CALL COUT
		0460		DEC HL
		0461	TWRT1	INC HL
		0462		LD A,(HL)
		0463		CALL COUT
		0464		ADD A,B
		0465		LD B,A
		0466		CALL CMPDH
		0467		JR NC,TWRT1-*
		0468		LD A,B
		0469		CALL COUT
		0470		CALL COUT
		0471		CALL COUT
		0472		SUB A
		0473		OUT (TABL),A
		0474		RET
		0475	COUT	PUSH AF
		0476		IN A,(TABL)
		0477		AND 20H
		0478		JR NZ,COUT+1-*
		0479		POP AF
		0480		OUT (TABL+1),A
		0481		RET
		0482	STRM	CALL SPACE
		0483		LD A,2
		0484		OUT (TABL),A
		0485	STRM1	LD A,0E6H
		0486		CALL COUT
		0487		JR STRM1-*
		0488	DELAY	EX (SP),HL
		0489		EX (SP),HL
		0490		DEC HL
		0491		LD A,L
		0492		OR H
		0493		JR NZ,DELAY-*
		0494		RET
		0495		ENDIF
		0496		;
E2DE	CD45E3	0497	VERIFY:	CALL TRPIN
E2E1	EB	0498		EX DE,HL
E2E2	2B	0499		DEC HL
E2E3	0B	0500		DEC BC
E2E4	23	0501	VRFY1:	INC HL
E2E5	03	0502		INC BC
E2E6	02	0503		LD (BC),A
E2E7	BE	0504		CP (HL)
E2E8	2814	0505		JR Z,VRFY2-*
E2EA	CD70E3	0506		CALL CRLF
E2ED	CD54E3	0507		CALL DHXOT
E2F0	CD7DE3	0508		CALL SPACE
E2F3	7E	0509		LD A,(HL)
E2F4	CD59E3	0510		CALL HEXOUT
E2F7	CD7DE3	0511		CALL SPACE
E2FA	02	0512		LD (BC),A
E2FB	CD59E3	0513		CALL HEXOUT
E2FE	CD06E3	0514	VRFY2:	CALL CMPDH

ADDR	CODE	STMT	SOURCE	STATEMENT
E301	30E1	0515		JR NC, VRFY1-\$
E303	C390E0	0516		JP EXEC
E306	F5	0517	CMPDH:	PUSH AF
E307	7A	0518		LD A, D
E308	BC	0519		CP H
E309	2007	0520		JR NZ, CMP1-\$
E30B	7B	0521		LD A, E
E30C	BD	0522		CP L
E30D	2003	0523		JR NZ, CMP1-\$
E30F	F1	0524		POP AF
E310	37	0525		SCF
E311	C9	0526		RET
E312	F1	0527	CMP1:	POP AF
E313	37	0528		SCF
E314	3F	0529		CCF
E315	C9	0530		RET
E316	CD22E3	0531	DHXIN:	CALL SPHIN
E319	E5	0532		PUSH HL
E31A	FE0D	0533		CP ODH
E31C	C425E3	0534		CALL NZ, HFXIN
E31F	EB	0535		EX DE, HL
E320	E1	0536		POP HL
E321	C9	0537		RET
E322	CD7DE3	0538	SPHIN:	CALL SPACE
E325	210000	0539	HEXIN:	LD HL, 0
E328	CD90E3	0540	HXIN1:	CALL CONIN
E32B	FE30	0541		CP '0'
E32D	F8	0542		RET M
E32E	FE47	0543		CP 'F'+1
E330	F0	0544		RET P
E331	FE3A	0545		CP '9'+1
E333	FA3BE3	0546		JP M, HXIN2
E336	FE41	0547		CP 'A'
E338	F8	0548		RET M
E339	CE09	0549		ADC A, 9
E33B	E60F	0550	HXIN2:	AND OFH
E33D	29	0551		ADD HL, HL
E33E	29	0552		ADD HL, HL
E33F	29	0553		ADD HL, HL
E340	29	0554		ADD HL, HL
E341	B5	0555		OR L
E342	6F	0556		LD L, A
E343	18E3	0557		JR HXIN1-\$
E345	CD22E3	0558	TRPIN:	CALL SPHIN
E348	EB	0559		EX DE, HL
E349	CD25E3	0560		CALL HEXIN
E34C	E5	0561		PUSH HL
E34D	CD25E3	0562		CALL HEXIN
E350	E5	0563		PUSH HL
E351	C1	0564		POP BC
E352	E1	0565		POP HL
E353	C9	0566		RET
E354	7C	0567	DHXOT:	LD A, H
E355	CD59E3	0568		CALL HEXOUT
E358	7D	0569		LD A, L
E359	F5	0570	HEXOUT:	PUSH AF
E35A	0F	0571		RRCA
E35B	0F	0572		RRCA

ADDR	CODE	STMT	SOURCE	STATEMENT
E35C	0F	0573		RRCA
E35D	0F	0574		RRCA
E35E	CD62E3	0575		CALL HXOT1
E361	F1	0576		POP AF
E362	E60F	0577	HXOT1:	AND 0FH
E364	C630	0578		ADD A,30H
E366	FE3A	0579		CP '9'+1
E368	FA85E3	0580		JP M,CONOUT
E36B	C607	0581		ADD A,7
E36D	C385E3	0582		JP CONOUT
E370	F5	0583	CRLF:	PUSH AF
E371	3E0D	0584		LD A,0DH
E373	CD85E3	0585		CALL CONOUT
E376	3E0A	0586		LD A,0AH
E378	CD85E3	0587		CALL CONOUT
E37B	F1	0588		POP AF
E37C	C9	0589		RET
E37D	F5	0590	SPACE:	PUSH AF
E37E	3E20	0591		LD A,20H
E380	CD85E3	0592		CALL CONOUT
E383	F1	0593		POP AF
E384	C9	0594		RET
E385	F5	0595	CONOUT:	PUSH AF
E386	DB11	0596		IN A,(KBDST)
E388	E601	0597		AND KBDOT
E38A	28FA	0598		JR Z,CONOUT+1-\$
E38C	F1	0599		POP AF
E38D	D310	0600		OUT (KBDST),A
E38F	C9	0601		RET
E390	DB11	0602	CONIN:	IN A,(KBDST)
E392	E602	0603		AND KBDIN
E394	28FA	0604		JR Z,CONIN-\$
E396	DB10	0605		IN A,(KBDST)
E398	E67F	0606		AND 7FH
E39A	FE61	0607		CP 61H
E39C	3806	0608		JR C,ECHO-\$
E39E	FE7C	0609		CP 7CH
E3A0	3002	0610		JR NC,ECHO-\$
E3A2	D620	0611		SUB 20H
E3A4	FE18	0612	ECHO:	CP 18H
E3A6	CA90E0	0613		JP Z,EXEC
E3A9	18DA	0614		JR CONOUT-\$
E3AB	7E	0615	PTXT:	LD A,(HL)
E3AC	FE03	0616		CP 03H
E3AE	C8	0617		RET Z
E3AF	CD85E3	0618		CALL CONOUT
E3B2	23	0619		INC HL
E3B3	18F6	0620		JR PTXT-\$
E3B5	DBFC	0621	BOOT	IN A,(WAIT)
E3B7	AF	0622		XOR A
E3B8	6F	0623		LD L,A
E3B9	67	0624		LD H,A
E3BA	3C	0625		INC A
E3BB	D3FA	0626		OUT (SECT),A
E3BD	3E8C	0627		LD A,8CH
E3BF	D3F8	0628		OUT (DCOM),A
E3C1	DBFC	0629	RLOOP	IN A,(WAIT)
E3C3	B7	0630		OR A

ADDR	CODE	STMT	SOURCE	STATEMENT
E3C4	F2CEE3	0631	JP	P.RDONE
E3C7	DBFB	0632	IN	A,(DDATA)
E3C9	77	0633	LD	(HL),A
E3CA	23	0634	INC	HL
E3CB	C3C1E3	0635	JP	RLOOP
E3CE	DBF8	0636	RDONE	IN A,(DSTAT)
E3D0	B7	0637	OR	A
E3D1	CA7D00	0638	JP	Z.SBOOT
E3D4	76	0639	HALT	
		0640	:	
		0641	END	

ADDR CODE STMT SOURCE STATEMENT

ALT1	E0F6	ALT2	E118	ALT3	E11B	ALTER	E0F3
BOOT	E3B5	CIN	E25F	CMP1	E312	CMPDH	E306
CONIN	E390	CONOUT	E385	COPY	E1B8	COPY0	E1C1
COPY1	E1C3	COUT	E2C0	CRLF	E370	DCOM	00F8
DDATA	00FB	DHXIN	E216	DHXOT	E354	DSTAT	00F8
DUMP	E11E	DUMP1	E121	DUMP2	E129	ECHO	E3A4
ERRO	E1FF	EXEC	E090	EXEC3	E092	EXEC4	E09D
FALSE	0000	FILL	E1A0	FILL0	E1AD	FILL1	E1AE
FTOP	E02E	FTOP1	E03B	FTOP2	E04B	GO	E0EF
HEXIN	E325	HEXOUT	E359	HXIN1	E328	HXIN2	E33B
HXOT1	E362	INIT	E021	INIT1	E04E	KBDDT	0010
KBDIN	0002	KBDOT	0001	KBDST	0011	KCTAPE	FFFF
LHXIN	E18E	LOAD	E172	LOAD0	E175	LOAD1	E17A
LOAD2	E182	MAP	E13C	MAP1	E141	MAP2	E14C
MAP3	E158	MAP4	E161	MON	0000	MS01	E063
PTXT	E3AB	RDONE	E3CE	RLOOP	E3C1	SBOOT	007D
SECT	00FA	SPACE	E37D	SPHIN	E322	STRM	E2CB
STRM1	E2D2	TAFE	0000	TAPST	0080	TARBEL	0000
TARBL	006E	TEST	E1CD	TEST0	E1D8	TEST1	E1DB
TEST2	E1E7	TLOAD	E217	TRD1	E24E	TRDA	E22F
TRDB	E231	TRDC	E23B	TREAD	E22B	TRPIN	E345
TRUE	FFFF	TSAVE	E28C	TUN0	E26F	TUN1	E274
TUN2	E274	TUN3	E283	TUNE	E268	TWRIT	E295
TWRT0	E29B	TWRT1	E2AB	VERIFY	E2DE	VRFY1	E2E4
VRFY2	E2FE	WAIT	00FC				

CROSS REFERENCE LISTING

SYMBOL	VALUE	TYPE	STMT	STATEMENT REFERENCES
ALT1	E0F6		0148	0167 0165
ALT2	E118		0144	0162
ALT3	E11B		0166	0158
ALTER	E0F3		0147	0112
BOOT	E3B5		0421	0140
CIN	E25F		0345	0356 0347 0342 0336 0326 0321
CMF1	E312		0527	0523 0520
CMFDH	E306		0517	0514 0387 0340 0260 0248 0175
CONIN	E370		0602	0604 0540 0108 0044
CONOUT	E385		0595	0618 0614 0598 0592 0587 0585 0582 0580 0364 0333
+				0316 0292 0106 0082 0045
COPY	E1B8		0251	0118
COPY0	E1C1		0254	0252
COPY1	E1C3		0256	0261
COUT	E2C0		0393	0406 0404 0396 0392 0391 0390 0384 0379 0375
CRLF	E370		0583	0506 0353 0305 0179 0169 0148 0104 0086 0079 0078
+				0049
DCOM	00F8		0035	0628
DDATA	00FB		0036	0632
DHXIN	E316		0531	0368 0311 0263 0238 0168
DHXOT	E354		0567	0507 0298 0212 0200 0170 0149 0089 0048
DSTAT	00F8		0037	0636
DUMP	E11E		0168	0114
DUMP1	E121		0169	0180
DUMP2	E129		0172	0179
ECHO	E3A4		0612	0610 0608
ERRO	E1FF		0296	0285
EXEC	E090		0099	0613 0516 0370 0317 0313 0295 0253 0250 0235 0213
+				0210 0176 0160 0020 0043
EXEC3	E092		0104	0144
EXEC4	E09D		0108	0110
FALSE	0000		0016	0019
FILL	E1A0		0238	0122
FILL0	E1AD		0245	0240
FILL1	E1AE		0246	0249
FTOP	E02E		0059	0071 0068
FTOP1	E03B		0067	0066
FTOP2	E04B		0080	
GO	E0EF		0145	0116
HEXIN	E325		0539	0562 0560 0534 0242 0229 0046
HEXOUT	E357		0570	0568 0513 0510 0304 0301 0174 0152 0047
HXIN1	E328		0540	0557
HXIN2	E33B		0550	0546
HXOT1	E362		0577	0575
INIT	E021		0053	0042
INIT1	E04E		0081	0085
KBDOT	0010		0030	0605 0600
KBDIN	0002		0031	0603
KBDOT	0001		0032	0597
KBDST	0011		0029	0602 0596 0057 0055
KCTAPE	FFFF		0020	0310 0135 0074
LHXIN	E18E		0229	0233 0231 0221 0217 0215
LOAD	E172		0214	0126
LOAD0	E175		0215	0219 0216

ADDR	CODE	STMT	SOURCE	STATEMENT
LOAD1	E17A	0217	0228	
LOAD2	E182	0221	0227	
MAP	E13C	0181	0124	
MAP1	E141	0183	0207	
MAP2	E14C	0192	0190	
MAP3	E158	0200	0197	
MAP4	E161	0204	0202 0194	
MON	0000	0025		
MSG1	E063	0095	0080	
PTXT	E3AB	0615	0620	
RDONE	E3CE	0636	0631	
RLOOP	E3C1	0627	0635	
SBOOT	007D	0038	0638	
SECT	00FA	0034	0626	
SPACE	E37D	0590	0538 0511 0508 0400 0350 0314 0302 0299 0214 0201	
			0172 0150 0107 0050	
SPHIN	E322	0538	0558 0531 0154 0147 0145	
STRM	E2CB	0400	0134	
STRM1	E2D2	0403	0407	
TAPE	0000	0027	0378 0348	
TAPST	0080	0028	0402 0394 0372 0352 0345 0319	
TARBEL	0000	0019	0410 0100 0091	
TARBL	006E	0039		
TEST	E1CD	0263	0120	
TEST0	E1D8	0269	0294	
TEST1	E1DB	0271	0278	
TEST2	E1E7	0281	0289	
TLOAD	E217	0311	0130	
TRD1	E24E	0335	0341	
TRDA	E22F	0320	0330 0328 0323	
TRDB	E231	0321	0325	
TRDC	E23B	0326		
TREAD	E22B	0318	0312 0051	
TRPIN	E345	0558	0497 0251	
TRUE	FFFF	0015	0020	
TSAVE	E28C	0368	0128	
TUN0	E26F	0353	0367	
TUN1	E274	0355	0366	
TUN2	E274	0356	0358	
TUN3	E283	0363	0361	
TUNE	E268	0350	0137	
TWRIT	E295	0371	0367 0052	
TWRTO	E29B	0374	0377	
TWRT1	E2AB	0302	0388	
VERIFY	E2DE	0497	0132	
VERFY1	E2E4	0501	0515	
VERFY2	E2FE	0514	0505	
WAIT	00FC	0033	0629 0621	

ERRORS=0000

APPENDIX B

CONSTRUCTION AND SOLDERING TIPS

Choose a well-lighted work space with enough room to place your tools, parts, and instructions where they will be easy to reach. If you have two light sources that can be adjusted, this will help eliminate shadows which interfere with seeing your work.

Familiarize yourself with all of the general operations to be performed. It might even help to do a dry run of sorts, getting everything together and following the procedures.

The tools you will need for each individual kit will be listed in the assembly instructions. A basic set would include: a low wattage soldering iron (20 watts or less—remember, you're working with microcomputers, not building bridges)—and with a 650-degree tip if you can get one; a holder which will keep you from accidentally touching the hot tip; a pair of wire cutters (also called dykes or side cutters, preferably beveled so that you can cut close to the board); a pair of needle-nose pliers; a damp sponge or a moistened cloth to use to wipe the soldering iron's tip; a magnifying glass to examine details, and a lead former to bend leads. The latter is available at most electronics parts houses in an inexpensive plastic version, or you can make your own out of wood. If you're into building lots of electronic kits, they're worth their weight in gold.

Arrange your tools in order of their frequency of use and orient them so they're easy to reach. Make sure that they are clean and in good working order.

Keep your work area clean and uncluttered.

Make sure that your chair is set at a proper height and is comfortable for your work station.

Try to keep food and drink away from your area. Always strive for neatness and uniformity. This means removing bits and pieces of scrap wire and solder blobs, as you work, so they don't become buried in your board and short something out. Inevitably, according to Murphy, they will sneak underneath IC sockets and if there's a place that's hardest to get to to fix, that's *exactly* where they'll lodge.

Soldering can cause several different kinds of problems in kit building. Heat can damage the PC board and the components, especially diodes and transistors, or create unwanted electrical connections. Most problems can be eliminated by using the right soldering iron (and the right solder—*rosin* core, *not* acid core), and by developing an efficient technique.

Parts are inserted on the component (front) side of the board. Soldering is done on the back side. This is always a rule, unless you are specifically directed otherwise in the assembly instructions.

If you plan on building many kits (and one memory board can be many kits), spend the few extra dollars to buy yourself a quality temperature-controlled soldering station. Spending the \$30 can save you from ruining a \$200 kit.

Use only **Rosin Core** solder when constructing electronic kits. Never, never, not **ever** use acid core—that's only for pipes and sheet metal. A solder with a high ratio of tin to lead is important, too. 60/40 is good—but 63/37 is better, and the difference will amaze you. If you can't get 63/37 at your local electronics parts house, JADE carries it, along with most of the other accessories you might need.

Make sure you have a well-tinned tip. A tip is well tinned when it has a thin film of solder coating on the surface of the iron. Oxide and resin build up as you work with it and the bright shiny look will disappear. That's what the wet sponge or moistened cloth is for. The iron should be wiped clean about every ten connections or so to get rid of that oxide and resin. Copper-tinned iron are fairly good, but gold-coated tips are much better.

Some DON'Ts: DON'T have any unnecessary items at your work station. DON'T use worn or damaged tools. NEVER solder equipment that is plugged in. DON'T use unknown cleaning solutions. DON'T pull on a solder joint to see if it's good. NEVER flip excess solder from the tip of your iron—use the sponge or cloth. NEVER put solder on your iron and then transfer it to a cold joint.

Heat both the component wire and the solder pad with the tip of the iron until it looks wet or liquid. Then touch the solder to the junction between the iron, the pad, and the wire. When the solder melts and flows onto the connection, quickly remove the iron's tip. Allow the joint to cool without moving any of the components. A good joint will be smooth and bright. A bad one will be a dull lead-looking glob of solder.

Avoid using too much solder! From our experience at repairing customer's boards, this is the sin most often committed. If little drops of solder appear on the opposite side of the board, you're either using too much solder or too much heat. Be extremely careful when you solder adjacent pads because the heat may cause the solder to flow between them, making a solder "bridge". Bridges are only good for crossing rivers—they don't belong on electronic boards. They make an unwanted electrical connection.

If you do find a bridge, the best way to remove it is to clean your iron on the dampened sponge or cloth and then touch the bridge with the clean hot tip until it

wets and sticks to the tip. Then get rid of it.

Excess wire can be removed with diagonal cutters. **WAIT** until the joint has cooled. Beware of flying pieces of wire. **Always use eye protection when soldering or cutting wire!**

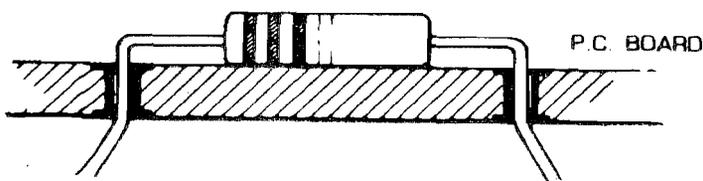
After you're all done, use Freon solvent to remove the flux. Flux is that brown stuff that gets on the board near your soldering joints, and it is formed of burned resin. Not only does it *look* bad (preventing your wonderful soldering job from looking all bright and shiny and seeing the light of day), it can cause electrical headaches as well, especially in higher-frequency circuits. Not only this, but it makes it much more difficult to find bridges and shorting flakes of solder, since the rosin hides the solder under an effective coverup. Leave coverups to the politicians—clean your board.

JADE technical support people have found that a board works about like it looks. If it's been put together with care and good workmanship, it will work just fine. In life, you only get out of it what you put into it, and it works the same with electronic kits.

COMPONENT INSTALLATION

Install all components in their proper location, and if polarity is important, observe the proper markings. The component should be installed flush with the circuit board, unless a clearance is specifically called for in the assembly instructions. This clearance is usually required for hot components that might burn or discolor the printed circuit board.

The lead should have a discernable length extending straight from the body of the component before beginning the bend. The component body shall not be damaged nor the body-to-lead seal be damaged by the forming operation. The component should be centered between the bends, although this is not a requirement. Where feasible, all forming should be done so that the part number is visible when installed in the printed circuit board.



Soldering techniques probably are the hardest to master of any electronic assembly technique. If you

have never soldered at all, it is probably best that you practice on some old scrap printed circuit board available at most electronic parts houses and surplus shops.

For electronic assembly, always use rosin core solder, not acid core solder. Acid core solder will corrode, and it's impossible to stop the corrosion once it's begun. It will eventually ruin the printed circuit board.

A soldering iron of small wattage (preferably 27 to 40 watts absolute maximum), should be used. Always keep the tip clean and free from dross (oxidized solder) by wiping on a moistened sponge or folded up Kleenex (moistened). Use small solder with a 60/40 ratio (60% tin and 40% lead).

When ready to solder a joint, apply heat to the joint first, then apply the solder to the opposite side of the joint from the iron. (See Figure B-1). Then remove the solder and finally the soldering iron. A good solder joint has an even flow of solder over the entire joint. A good joint will have a bright glistening look. A bad solder joint, commonly called a "cold" solder joint, will have a dull appearance. Also, do not move the part or the lead while the solder is cooling or a cold or fractured solder joint will result (see Figure B-2a-c).

Apply solder to the opposite side of the lead from the soldering iron's position.

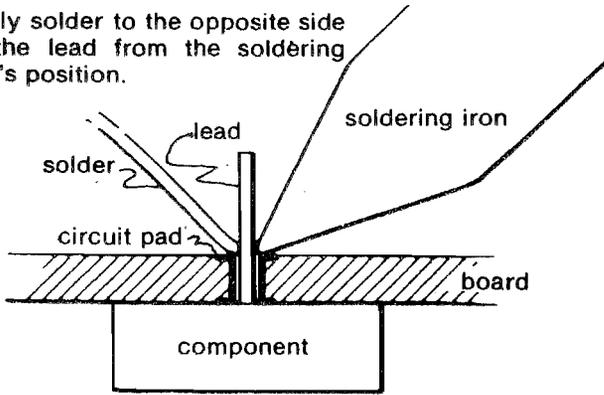


Figure B-1 Illustrates proper soldering techniques

The fillet is well-formed. It is concave and well above the surface of the pad.

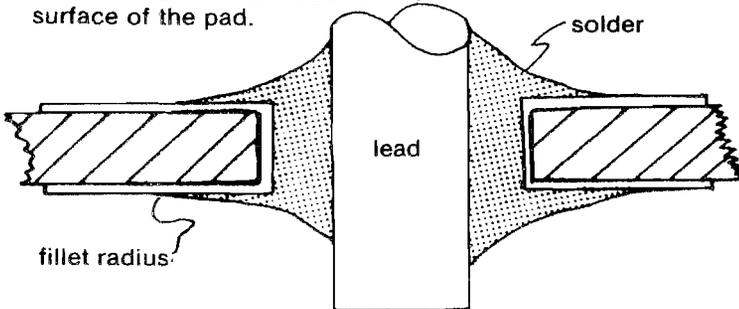


Figure B-2 (a) Illustrates an Optimum Solder Joint

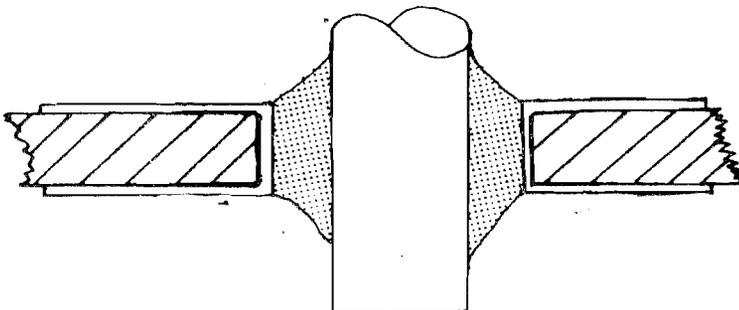


Figure B-2 (b) Illustrates the minimum solder acceptable

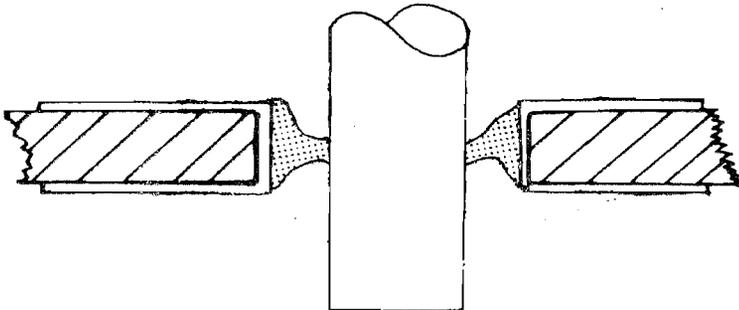


Figure B-2 (c) Illustrates insufficient solder.

Lead Forming

Lead forming is performed by grasping the body of the part with the fingers of one hand. With the other hand holding long-nose pliers, grasp the lead near the body with the taper of the pliers defining the length of lead from the body of the part to the lead. Bend the lead with the opposite hand to form the bend as in Figure B-3.

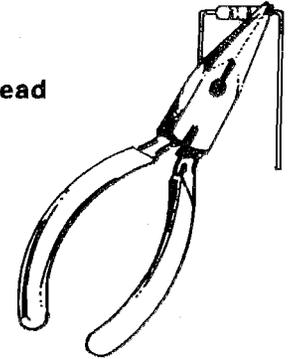
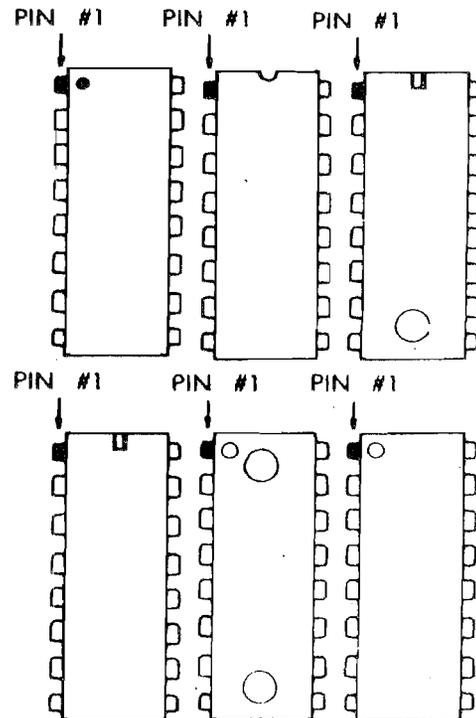


Figure B-3 Illustrates lead forming techniques.



PARTS LIST FOR JADE BIG Z CPU - REVISION C BOARD

Item No	Qty/ Assy	Jade Part No.	Description
1	1	CPU-30200D	Manual, Big Z Revision C
2	1	CPU-30200B	PC Board, Big Z Revision C, 2/4 MHz
3	1	ICM-Z80A	Microprocessor IC, Z80A, 4MHz - U16
4	1	ICS-8251	USART, 8251 - U3
5	1	ICS-MC14411	Baud Rate Generator, MC14411 - U2
6	9	ICT-N8T97	Hex TS Buffer, 8T97/74367/8097/74LS367 - U6,17,25,29,35-39
7	2	ICM-DM8131N	6-Bit Comparator, DM8131 - U24, 34
8	3	ICT-7475	Quad Latch, 7475/74LS75 - U40, 26, 27
9	2	ICT-7474	Dual D Flipflop, 7474/74LS74 - U11, 20
10	1	ICT-74121	One-shot, 74121/74LS121 - U5
11	1	ICT-7432	Quad 2-input OR, 7432/74LS32 - U14
12	2	ICT-7400	Quad 2-input NAND, 7400/74LS00 - U10, 22
13	2	ICT-7408	Quad 2-input AND, 7408/74LS08 - U7, 41
14	1	ICT-7410	Triple 3-input NAND, 7410/74LS10 - U4
15	1	ICT-7402	Quad 2-input NOR, 7402/74LS02 - U8
16	4	ICT-7404	Hex Inverter, 7404/74LS04 - U15, 18, 21, 30
17	1	ICT-1488	RS232 Driver, MC1488/75188 - U12
18	1	ICT-1489	RS232 Receiver, MC1489/75189 - U9
19	1	ICL-LM7805	+5V Regulator, LM340T5/7805 - VR4
20	1	ICL-LM7812	+12V Regulator, LM340T12/7812 - VR3
21	1	ICL-LM7905	-5V Regulator, LM320T5/7905 - VR1
22	1	ICL-LM7912	-12V Regulator, LM320T12/7912 - VR2
23	1	CRY-O40	Crystal, 4.0000 MHz - Y1
24	1	CRY-O18L	Crystal, 1.8432 MHz - Y2
25	1	SKL-4001	Socket, 40-pin low profile
26	1	SKL-2801	Socket, 28-pin low profile
27	2	SKL-2401	Socket, 24-pin low profile
28	18	SKL-1601	Socket, 16-pin low profile
29	16	SKL-1401	Socket, 14-pin low profile
30	3	SWD-108	DIP Switch, 8-position - U1, 23, 33
31	1	SWX-101	Switch, SPDT, low profile, T-U-V switch
32	3	RCD-16154.7K	Resistor Pack, 15-resistor, 16-pin 4.7K pullups - U28, 31, 32
33	7	RCQ-4.70K	Resistor, 4.7K $\frac{1}{4}$ -watt - R1, 3, 7, 8, 9, 13, 14
34	1	RCQ-330.0	Resistor, 330 ohm, $\frac{1}{4}$ watt - R5
35	3	RCQ-1.0K	Resistor, 1K, $\frac{1}{4}$ -watt - R4, 10, 11
36	1	RCQ-2.70K	Resistor, 2.7K $\frac{1}{4}$ watt - R2
37	1	RCQ-22.0M	Resistor, 22 Meg, $\frac{1}{4}$ -watt - R6
38	1	RCQ-6.80K	Resistor, 6.8K, $\frac{1}{4}$ watt - R12
39	15	CAD-104P500	Capacitor, disk ceramic, 0.1uf - C1-15
40	1	CAA-101M639	Capacitor, 100uf axial electrolytic/50-100uf - C22
41	3	CAD-102P500	Capacitor, disk ceramic, 0.001uf - C23, 26, 27
42	2	CAD-101P500	Capacitor, 100pf mica - C24, C25
43	6	CAT-15P250	Capacitor, tantalum, 1.5uf/1.5-3.3uf - C16-21
44	1	HDH-36100	Heat Sink, AHM, TO-220 style (use at VR4)
45	4	- - - -	Screws, 6-32 x $\frac{1}{2}$ "
46	4	- - - -	Nuts, Hex, #6
47	4	- - - -	Washers, Lock, #6

Last U Number = U41
 Last R Number = R14
 Last C Number = C27
 Last Y Number = Y2
 Last V Number = VR4

JADE COMPUTER PRODUCTS

ENGINEERING PRODUCT-IMPROVEMENT BULLETIN - CPU-30201

BIG Z CPU CARD - ECN 101

2 December, 1980

Problem: Erratic reset operation.

Symptoms: The CPU fails to reset reliably when the reset line is pulled low, although it will reset properly on power-on.

Cause: Excessive time constant on RC network on input to IC U21, pin 1 (reset buffer). The time constant of the power-on/reset network is approximately 0.5 seconds (470 milliseconds). This delay is required for operation with front-panel type systems, but it is lengthy for turnkey systems using an on-board EPROM monitor. The specification for the Z80 CPU is a minimum of 4 clock cycles.

Cure: Remove C22, a 100 microfarad electrolytic capacitor, and install a 1 to 10 microfarad tantalum capacitor in its place. The lower value capacitor may cause the board to fail to reset when doing a power-on without striking the reset switch on the mainframe. If this is experienced, the value of C22 should be increased, up to 22 microfarads. The optimum value may be found for each particular system by experimentation.

JADE COMPUTER PRODUCTS

ENGINEERING PRODUCT-IMPROVEMENT BULLETIN - CPU-30201

BIG Z CPU CARD - ECN 102

2 December, 1980

Problem: Timing Problems Associated with Status Signal Delay.

Symptoms: The CPU card fails to operate with some dynamic memory cards at 4 MHz, and operates erratically with some disk controller cards at all operating clock rates.

Cause: In an attempt to make the BIG Z CPU as versatile as possible, it was designed to operate with a front panel board of the Imsai type. This requires latching the status signals SWO*, sMEMR and sINP. This latching is done by IC U40, a 7475/74LS75 IC, clocked by the signal pSYNCH. The manual fails to mention that this takes the CPU board out of IEEE timing specification.

Cure: Remove IC U40 and install a 16-pin dip header with jumpers installed between pins 2/16, 3/15, 6/10 and 7/9. This removes the latch and does not introduce a pSYNCH delay for these signals.

Inter-card Compatibility:

The above modification must be done to allow the BIG Z CPU to operate with an S.D. Systems Expandoram II at either 2 or 4 MHz. It must be done to ensure reliable operation with the JADE Double D Disk Controller, and other types of disk controller cards (not required for any S.D. Systems disk controller or for the Expandoram I when operated at 2 MHz).

JADE COMPUTER PRODUCTS

ENGINEERING PRODUCT-IMPROVEMENT BULLETIN - CPU-30201

BIG Z CPU CARD - ECN 103

2 December, 1980

Revision C level, manufacturing level 5 and above

Problem: Owner's manual errata

Checkout Procedures & Troubleshooting Tips - page 14.

In paragraph 10, step 1, it is stated that pins 1-5 and 30-40 as well as the data pins on the Z80 should show high during reset. In actuality, they are tri-stated, and the more sophisticated logic probes, as well as oscilloscopes, will show them as somewhere in the indeterminate range.

In step 2, it is stated (incorrectly) that pin 24 of the Z80 should be low. In reality, it should be high unless you have selected the EPROM wait state option or installed the M1 wait state option, in which case it will be high with low-going pulses. In the same step it is stated that pin 27 (M1*) of the Z80 should be low. In reality, it will be high with low-going pulses. The above instructions were intended for those people with primitive logic probes, and they are correct as stated; however, the manual should be changed to reflect a more accurate state of affairs for those people who have oscilloscopes or newer types of logic probes.

EPROM Tables - pages 17 & 18

Although it is not specifically stated in the manual, the purpose of the Xes is to indicate a switch CLOSED position, or ON position. A properly installed switch will have its 1 position facing the S100 bus. The tables are correct if the switch positions marked X are closed.

NOTE however, the function of switch positions 6, 7 and 8. These switches are for the purpose of making the EPROM slot as versatile as possible. Switch 8 routes Address Line A10 to one input to the comparator 8131 at U34, as well as one side of switch U33, position 7. If switches 7 and 8 are both closed, the effect is to ground A10, preventing it from ever going high. This is neither very effective, nor particularly good for the Z80 CPU chip. If you are wanting to compare A10 to a zero condition, turn switch position 8 ON, turn switch position 7 OFF (removing the ground from A10), and turn switch position 6 ON, grounding the B-side input to the comparator and forcing a comparison to a ZERO state. Conversely, if you want to compare A10 to a high or 1 state, turn switch 8 ON, turn switch 7 OFF and turn switch 6 OFF. The pullup resistor will then pull the B-side comparator input corresponding to A10 high, forcing a comparison equal when A10 goes to a high or 1 state. To ignore the state of A10, turn switch 8 OFF, and turn switches 7 and 6 both ON. Refer to the schematics for an understanding of this.

Monitor Listing - The monitor program listing has been upgraded to remove a few bugs in the original. A new revised listing is available for \$15 from JADE.

Schematic - despite customer calls to the contrary, there are only 2 minor errors in the schematic diagram. Error 1: the arrow on the data-out buffers U25 and U37 is shown pointing the wrong way--picky, picky. Error 2: (this

one should cause problems only to those engineering types who attempt to do things from the schematic rather than following the written instructions. On page 2 of the schematic, the labels are reversed on the jumper leading from +12V to pin 19 of the EPROM slot. The +12V side is labeled M, where it should properly be labeled F, and likewise, the EPROM side of the jumper is labeled F where it should correctly be labeled M. All instructions for installing the different types of EPROMS as listed in the OPTIONS section of the manual are correct. Follow the instructions.

Options Section - pages 10 and 11

- a) 2708-type EPROM - all instructions are correct.
- b) 2716 T1 (tri-voltage) type EPROM:
 - Step 4, which reads "Set switches 1 and 7 on U33 to ON" applies to revision A and B level boards only--for a C-level revision step 4 should read: "Set switches 6 and 7 on U33 to ON."
- c) 2716 single-voltage EPROM:
 - Step 7, which reads "Set switches 1 and 7 on U33 to ON" applies to revision A and B level boards only--for a C-level revision board, step 7 should read "Set switches 6 and 7 on U33 to ON."
 - Step 8, which reads "Set switch 8 on U33 to ON" should read "Set switch 8 on U33 to OFF. (typographic error.)
- d) 2732-type EPROM:
 - Step 8, which reads "Set switch 1, 2 and 7 on U33 to ON" applies to revision A and B level boards only--for a C level revision board, step 8 should read: "Set switches 5, 6 and 7 on U33 to ON.
- e) Under Option 2--M1 Wait State Option, there is a printer's error in step 2. Step 2 should read: "Uninstall a jumper from R to P (not F). Delete step 3.
- f) Disregard Option 3 entirely--this ROM is no longer available.

A very careful review of the manual by the JADE Engineering Staff has determined that these are the only existing errors in the Big Z CPU Manual. Future printings should incorporate these changes.

JADE COMPUTER PRODUCTS

ENGINEERING PRODUCT-IMPROVEMENT BULLETIN - CPU-30201

2 December, 1980

BIG Z CPU CARD - ECN 104

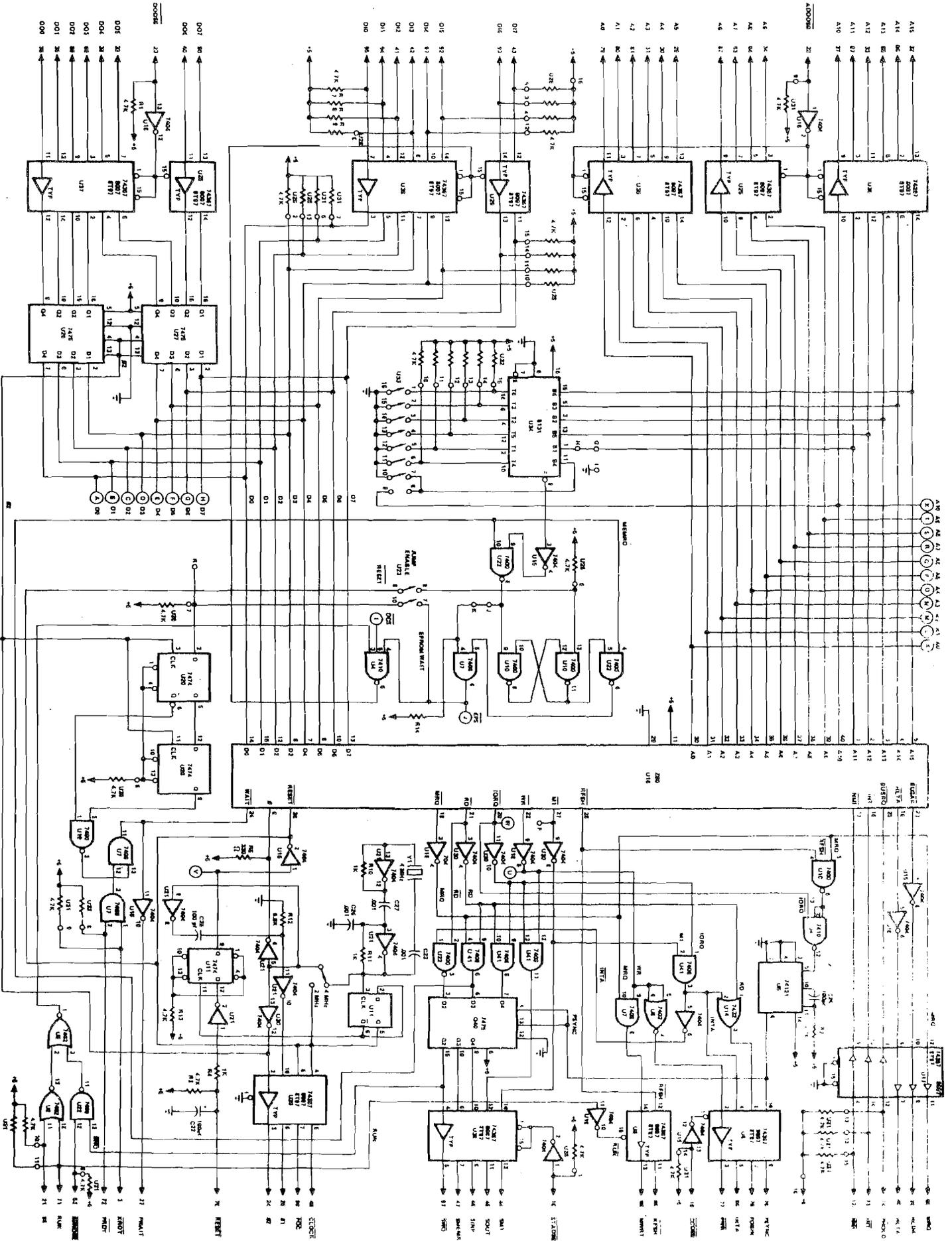
Problem: The CPU will not respond through the serial port at 4 MHz, although it operates reliably at 2 MHz.

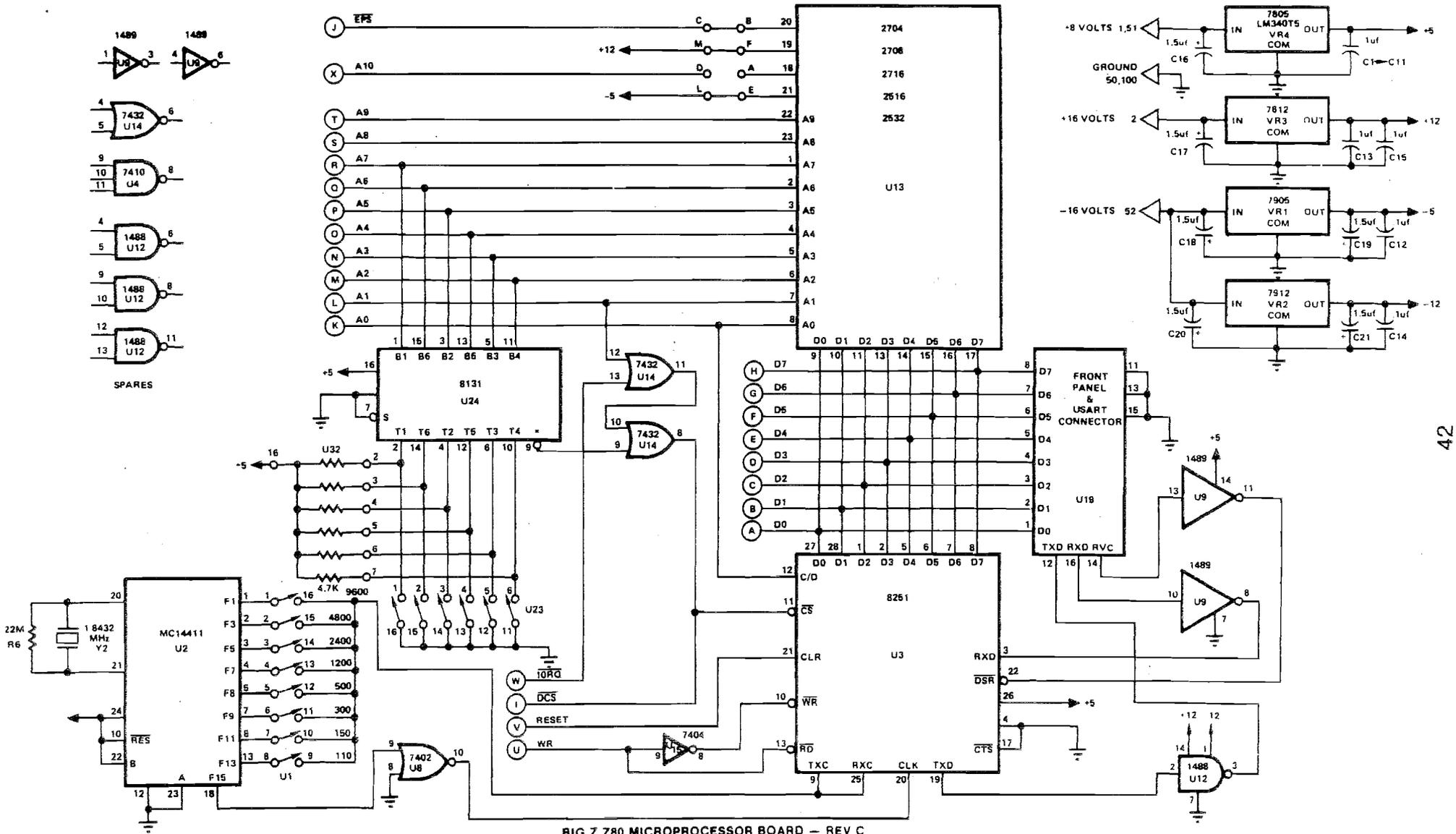
Symptoms: The serial port throws garbage on the screen, or it fails to operate entirely.

Cause: Installation of incorrect USART chip (8251)
We have encountered problems, primarily with customers who have purchased bare boards but with some kit customers as well, with the USART installed at U3. If the USART is not specifically rated to operate at 4 MHz, it usually won't. This holds especially true for some particular brands of 8251 USART. Also, we have seen earlier types of 8251 USART, purchased on the surplus market, installed. The earlier 8251s were very unreliable, especially at higher clock rates, and some brands of 8251s of the newer version are very erratic at high clock rates.

Cure: Install a B-type USART, specifically rated at 4 MHz operation.

Alternate: Install ECN 105 (USART Wait State).
(The above solution is not the preferable one!)





BIG Z Z80 MICROPROCESSOR BOARD - REV C
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